



Introduction

The bootloader is stored in the internal boot ROM memory (system memory) of STM32 devices. It is programmed by ST during production. Its main task is to download the application program to the internal Flash memory through one of the available serial peripherals (USART, CAN, USB, etc.). A communication protocol is defined for each serial interface, with a compatible command set and sequences.

This document applies to the products listed in [Table 1](#). They will be referred to STM32 throughout the document.

Table 1. Application products

Type	Part number or product series
Microcontroller	STM32F051x6, STM32F051x8
	STM32 F1 Mainstream
	STM32 F2 Hi-performance
	STM32F40xx and STM32F41xx
	STM32L151xx, STM32F152xx, and STM32F162xx

The main features of the bootloader are the following:

- It uses an embedded serial interface to download the code with a predefined communication protocol
- It transfers and updates the Flash memory code, the data, and the vector table sections

This application note presents the general concept of the bootloader. It describes the supported peripherals and hardware requirements to be considered when using the bootloader of any STM32 device currently in production. However the specifications of the low-level communication protocol for each supported serial peripheral are documented in separate documents. For specifications of the USART protocol used in the bootloader please refer to AN3155. For the specification of CAN protocol used in the bootloader please refer to AN3154. For the specification of DFU (USB Device) protocol used in the bootloader please refer to AN3156.

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1 Related documents

All the documents mentioned below are available from <http://www.st.com>:

- Datasheets
 - Low, medium and high-density STM32F101xx and STM32F103xx datasheets
 - Low, medium and high-density STM32F100xx and STM32F102xx datasheets
 - STM32F105xx/107xx connectivity line datasheet
 - XL-density STM32F101xx and STM32F103xx datasheets
 - STM32L151xx and STM32F152xx datasheet
 - STM32F162xx datasheet
 - STM32F205xx STM32F207xx and STM32F215xx STM32F217xx datasheets
 - STM32F405xx STM32F407xx and STM32F415xx STM32F417xx datasheets
 - STM32F051x6 and STM32F051x8 devices datasheets
- Reference manuals
 - STM32F101xx, STM32F102xx, STM32F103xx and STM32F105xx/107xx reference manual (RM0008)
 - Low, medium and high-density STM32F100xx value line reference manual (RM0041)
 - STM32L151xx, STM32L152xx, and STM32L162xx advanced ARM-based 32-bit MCUs reference manual (RM0038)
 - STM32F205xx, STM32F207xx, STM32F215xx and STM32F217xx advanced ARM-based 32-bit MCUs reference manual (RM00033)
 - STM32F405xx, STM32F407xx, STM32F415xx and STM32F417xx advanced ARM-based 32-bit MCUs reference manual (RM00090)
 - STM32F051xx advanced ARM-based 32-bit
- Flash programming manuals
 - STM32F101xx, STM32F102xx, STM32F103xx and STM32F105xx/107xx Flash programming manual (PM0042)
 - Low, medium and high-density STM32F100xx value line Flash programming manual (PM0063)
 - XL-density STM32F101xx and STM32F103xx Flash programming manual (PM0068)
 - STM32L151xx, STM32L152xx, and STM32L162xx Flash programming manual (PM0062)
 - STM32F205xx, STM32F207xx, STM32F215xx and STM32F217xx Flash programming manual (PM0059)
 - STM32F405xx, STM32F407xx, STM32F415xx and STM32F417xx Flash programming manual (PM0081)

2 Glossary

Low-density devices are STM32F101xx, STM32F102xx and STM32F103xx microcontrollers where the Flash memory density ranges between 16 and 32 Kbytes.

Medium-density devices are STM32F101xx, STM32F102xx and STM32F103xx microcontrollers where the Flash memory density ranges between 64 and 128 Kbytes.

High-density devices are STM32F101xx and STM32F103xx microcontrollers where the Flash memory density ranges between 256 and 512 Kbytes.

Connectivity line devices are STM32F105xx and STM32F107xx microcontrollers.

Low-density value line devices are STM32F100xx microcontrollers where the Flash memory density ranges between 16 and 32 Kbytes.

Medium-density value line devices are STM32F100xx microcontrollers where the Flash memory density ranges between 64 and 128 Kbytes.

High-density value line devices are STM32F100xx microcontrollers where the Flash memory density ranges between 256 and 512 Kbytes.

XL-density devices are STM32F101xx and STM32F103xx microcontrollers where the Flash memory density ranges between 768 Kbytes and 1 Mbyte.

Medium-density ultralow power devices are STM32L151xx and STM32L152xx microcontrollers where the program memory density ranges between 64 and 128 Kbytes.

High-density ultralow power devices are STM32L151xx, STM32L152xx and STM32L162xx microcontrollers where the program memory density size is 384 Kbytes.

STM32F2xxx devices are STM32F215xx, STM32F205xx, STM32F207xx and STM32F217xx microcontrollers with a Flash memory density ranging from 128 to 1024 Kbytes.

STM32F4xxx devices are STM32F415xx, STM32F405xx, STM32F407xx and STM32F417xx microcontrollers with a Flash memory density ranging from 512 to 1024 Kbytes.

STM32F051xx devices are STM32F051x6, STM32F051x8 microcontrollers where the Flash memory density ranges between 32 and 64 Kbytes.

3 General bootloader description

3.1 Bootloader activation

The bootloader is automatically activated by configuring the BOOT0 and BOOT1 pins in the specific “System memory” configuration (see [Table 2](#)) and then by applying a reset.

Depending on the used pin configuration, the Flash memory, system memory or SRAM is selected as the boot space, as shown in [Table 2](#) below.

In some products, BOOT1 is not an I/O but a bit in the option byte area. This is the case for the STM32F05x devices where BOOT1 is configured through nBoot1 bit in the option bytes.

- When nBoot1 bit is set to 1, it corresponds to BOOT1 reset to 0 in [Table 2](#)
- When nBoot1 bit is reset to 0, it corresponds to BOOT1 set to 1 in [Table 2](#).

Table 2. Boot pin configuration

Boot mode selection pins		Boot mode	Aliasing
BOOT1	BOOT0		
X	0	User Flash memory	User Flash memory is selected as the boot space
0	1	System memory	System memory is selected as the boot space
1	1	Embedded SRAM	Embedded SRAM is selected as the boot space

[Table 2](#) shows that the STM32 microcontrollers enter System memory boot mode if the BOOT pins are configured as follows:

- BOOT0 = 1
- BOOT1 = 0

The values on the BOOT pins are latched on the fourth rising edge of SYSCLK after a reset.

3.2 Exiting System memory boot mode

System memory boot mode must be exited in order to start execution of the application program. This can be done by applying a hardware reset. During reset, the BOOT pins/bits (BOOT0 and BOOT1) must be set at the proper levels to select the desired boot mode (see [Table 2](#)). Following the reset, the CPU starts code execution from the boot memory located at the bottom of the memory address space starting from 0x0000 0000.

3.3 Bootloader identification

Depending on the STM32 device used, the bootloader may support one or more embedded serial peripherals used to download the code to the internal Flash memory. The bootloader identifier (ID) provides information about the supported serial peripherals.

For a given STM32 device, the bootloader is identified by means of the:

1. **Bootloader (protocol) version:** version of the serial peripheral (USART, CAN, USB, etc.) communication protocol used in the bootloader. This version can be retrieved using the bootloader Get Version command.
2. **Bootloader identifier (ID):** version of the STM32 device bootloader, coded on one byte in the **0xXY** format, where:
 - **X** specifies the embedded serial peripheral(s) used by the device bootloader:
 - X = 1: only one USART is used
 - X = 2: two USARTs are used
 - X = 3: two USARTs, one CAN and DFU are used
 - X = 4: two USARTs and DFU are used
 - **Y** specifies the device bootloader version

Let us take the example of a bootloader ID equal to 0x10. This means that it is the first version of the device bootloader that uses only one USART.

The bootloader ID is programmed in the last two bytes of the device system memory and can be read by using the bootloader “Read memory” command or by direct access to the system memory via JTAG/SWD.

The table below provides identification information about the bootloader embedded in STM32 devices.

Table 3. Embedded bootloaders

Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
		ID	Memory location	
Low-density	USART1	NA	NA	USART (V2.2)
Medium-density	USART1	NA	NA	USART (V2.2)
High-density	USART1	NA	NA	USART (V2.2)
Connectivity line	USART1 / USART2 (remapped) / CAN2 (remapped) / DFU (USB Device)	NA	NA	USART (V2.2 ⁽¹⁾) CAN (V2.0) DFU(V2.2)
Medium-density value line	USART1	V1.0	0x1FFFF7D6	USART (V2.2)
High-density value line	USART1	V1.0	0x1FFFF7D6	USART (V2.2)
XL-density	USART1/USART2 (remapped)	V2.1	0x1FFFF7D6	USART (V3.0)
Medium-density ultralow power line	USART1/USART2	V2.0	0x1FF00FFE	USART (V3.0)

Table 3. Embedded bootloaders (continued)

Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
		ID	Memory location	
High-density ultralow power line	USART1/USART2/DFU (USB Device FS)	V4.5	0x1FF01FFE	USART (V3.1)/ DFU (V2.2)
STM32F2xxx devices	USART1/USART3	V2.0	0x1FFF77DE	USART (V3.0)
	USART1/USART3/CAN2/DFU (USB Device FS)	V3.3	0x1FFF77DE	USART (V3.1)/ CAN (V2.0)/ DFU (V2.2)
STM32F4xxx devices	USART1/USART3/CAN2/DFU (USB Device FS)	V3.1	0x1FFF77DE	USART (V3.1)/ CAN (V2.0)/ DFU (V2.2)
STM32F051xx devices	USART1/USART2	V2.1	0x1FFF7FA6	USART (V3.1)

1. For connectivity line devices, the USART bootloader returns V2.0 instead of V2.2 for the protocol version. For more details please refer to the "STM32F105xx and STM32F107xx revision Z" errata sheet available from <http://www.st.com>.

4 STM32F100xx, STM32F101xx, STM32F102xx, STM32F103xx, medium-density and high-density value line bootloader

Throughout this section **STM32F10xxx** will be used to refer to low-density, medium-density, high-density STM32F101xx and STM32F103xx devices, to low- and medium-density STM32F102xx devices, to low-, medium-, and high-density STM32F100x, and to medium and high-density value line devices.

4.1 Bootloader configuration

The bootloader embedded in STM32F10xxx devices supports only one interface: the USART1.

The following table shows the required STM32F10xxx hardware resources used by the bootloader in System memory boot mode.

Table 4. STM32F10xxx configuration in System memory boot mode

Feature/Peripheral	State	Comment
Clock source	HSI enabled	The system clock is equal to 24 MHz using the PLL
USART1_RX pin	Input	PA10 pin: USART1 receives
USART1_TX pin	Output push-pull	PA9 pin: USART1 transmits
SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.
USART1	Enabled	Once initialized the USART1 configuration is: 8-bits, even parity and 1 Stop bit
RAM	-	512 bytes starting from address 0x2000 0000 are used by the bootloader firmware
System memory	-	2 Kbytes starting from address 0x1FFF F000, contain the bootloader firmware
IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (in case the hardware IWDG option was previously enabled by the user)

The system clock is derived from the embedded internal high-speed RC, no external quartz is required for the bootloader code.

After downloading the application binary, if you choose to execute the Go command, the peripheral registers used by the bootloader (shown in the above table) are not initialized to their default reset values before jumping to the user application. They should be reconfigured in the user application if they are used. So, if the IWDG is being used in the application, the IWDG prescaler value has to be adapted to meet the requirements of the application (since the prescaler was set to its maximum value by the bootloader).

4.2 Bootloader hardware requirements

The hardware required to put the STM32 into System memory boot mode consists of any circuitry, switch or jumper, capable of holding the BOOT0 pin high and the BOOT1 pin low during reset.

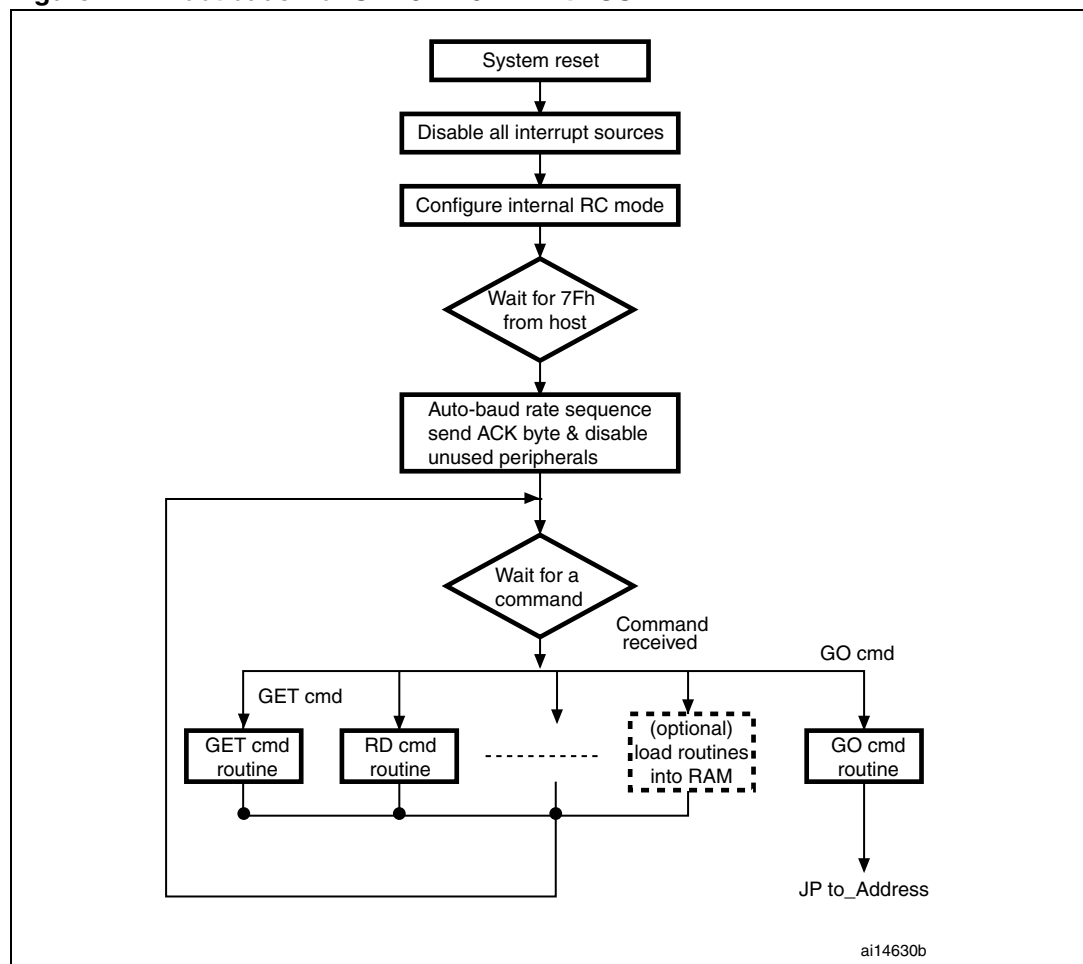
To connect to the STM32 during System memory boot mode, an RS232 serial interface (example, ST3232 RS232 transceiver) has to be directly linked to the USART1_RX (PA10) and USART1_TX (PA9) pins.

Note: **USART1_CK**, **USART1_CTS** and **USART1_RTS** pins are not used, therefore user can use these pins for other peripherals or GPIOs.

For more details about hardware recommendations, refer to application note AN2586: “STM32 hardware development: getting started”, available from the STMicroelectronics website: <http://www.st.com>.

4.3 Bootloader selection

Figure 1. Bootloader for STM32F10xxx with USART1



Once System memory boot mode is entered and the microcontroller has been configured as described above, the bootloader code begins to scan the USART1_RX line pin, waiting to receive the 0x7F data frame: one start bit, 0x7F data bits, even parity bit and one stop bit.

The duration of this data frame is measured using the SysTick timer. The count value of the timer is then used to calculate the corresponding baud rate factor with respect to the current system clock.

Next, the code initializes the serial interface accordingly. Using this calculated baud rate, an acknowledge byte (0x79) is returned to the host, which signals that the STM32F10xxx is ready to receive user commands.

4.4 Bootloader version

[Table 5](#) lists the bootloader versions of the STM32F10xxx devices.

Table 5. STM32F10xxx bootloader versions

Bootloader version number	Description
V2.0	Initial bootloader version.
V2.1	<ul style="list-style-type: none"> – Updated Go Command to initialize the main stack pointer – Updated Go command to return NACK when jump address is in the Option byte area or System memory area – Updated Get ID command to return the device ID on two bytes – Update the bootloader version to V2.1
V2.2	<ul style="list-style-type: none"> – Updated Read Memory, Write Memory and Go commands to deny access with a NACK response to the first 0x200 bytes of RAM memory used by the bootloader – Updated Readout Unprotect command to initialize the whole RAM content to 0x0 before ROP disable operation

5 STM32F105xx and STM32F107xx device bootloader

5.1 Bootloader configuration

The bootloader embedded in the STM32F105xx and STM32F107xx devices supports four serial peripherals: USART1, USART2, CAN2, and DFU (USB). This means that four serial peripherals are supported: USART1, USART2, CAN2 and DFU (USB).

The following table shows the hardware resources required by STM32F105xx and STM32F107xx devices used by the bootloader in System memory boot mode.

Table 6. STM32F105xx/107xx configuration in System memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz using the PLL. This is used only for USART1 and USART2 bootloaders and during CAN2, USB detection for CAN and DFU bootloaders (Once CAN or DFU bootloader is selected, the clock source will be derived from external crystal).
		HSE enabled	The external clock is mandatory only for DFU and CAN bootloaders and it must provide one of the following frequencies: 8 MHz, 14.7456 MHz or 25 MHz. For CAN Bootloader, the PLL is used only to generate 48 MHz when 14.7456 MHz is used as HSE. For DFU Bootloader, the PLL is used to generate a 48 MHz system clock from all supported external clock frequencies.
		-	The clock security system (CSS) interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock will generate system reset.
	IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (in case the hardware IWDG option was previously enabled by the user).
	System memory	-	18 Kbytes starting from address 0x1FFF B000, contain the bootloader firmware
	RAM	-	4 Kbytes starting from address 0x2000 0000 are used by the bootloader firmware.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is: 8-bits, even parity and 1 Stop bit
	USART1_RX pin	Input	PA10 pin: USART1 receive
	USART1_TX pin	Output push-pull	PA9 pin: USART1 transmit
	USART2_RX (PD6), CAN2_RX (PB5), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins must be kept at a high or low level during the detection phase.		

Table 6. STM32F105xx/107xx configuration in System memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1 and USART2 bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is: 8-bits, even parity and 1 Stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 receive (remapped pin)
	USART2_TX pin	Output push-pull	PD5 pin: USART2 transmit (remapped pin)
	USART1_RX (PA10), CAN2_RX (PB5), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins must be kept at a high or low level during the detection phase.		
CAN2 bootloader	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during the CAN bootloader execution because in STM32F105xx and STM32F107xx devices, CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 receives (remapped pin)
	CAN2_TX pin	Output push-pull	PB6 pin: CAN2 transmits (remapped pin)
	USART1_RX (PA10), USART2_RX (PD6), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins must be kept at a high or low level during the detection phase.		
DFU bootloader	USB OTG FS	Enabled	USB OTG FS configured in Forced Device mode
	OTG_FS_VBUS pin	Input or alternate function, automatically controlled by the USB OTG FS controller	PA9: Power supply voltage line
	OTG_FS_DM pin		PA11: USB Send-Receive data line
	OTG_FS_DP pin		PA12: USB Send-Receive data line
	Interrupts	Enabled	USB_OTG_FS interrupt vector is enabled and used for USB DFU communication.
	USART1_RX (PA10), USART2_RX (PD6) and CAN2_RX (PB5) pins must be kept at a high or low level during the detection phase.		

The system clock is derived from the embedded internal high-speed RC for USARTx bootloader. This internal clock is used also for DFU and CAN bootloaders but only for the selection phase. An external clock (8 MHz, 14.7456 MHz or 25 MHz.) is required for DFU and CAN bootloader execution after the selection phase.

After downloading the application binary, if you choose to execute the Go command, all peripheral registers used by the bootloader (shown in the above table) will be initialized to their default reset values before jumping to the user application.

If the user application uses the IWDG, the IWDG prescaler value has to be adapted to meet the requirements of the application (since the prescaler was set to its maximum value by the bootloader).

5.2 Bootloader hardware requirements

The hardware required to put the STM32F105xx and STM32F107xx into System memory boot mode consists of any circuitry, switch or jumper, capable of holding the BOOT0 pin high and the BOOT1 pin low during reset.

To connect to the STM32F105xx and STM32F107xx during System memory boot mode, the following conditions have to be verified:

- The RX pins of the unused peripherals in this bootloader have to be kept at a known (low or high) level, and should not be left floating during the detection phase as described below:
 - If USART1 is used to connect to the bootloader: the USART2_RX (PD6), CAN2_RX (PB5), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins have to be kept at a high or low level and must not be left floating during the detection phase.
 - If USART2 is used to connect to the bootloader: the USART1_RX (PA10), CAN2_RX (PB5), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins have to be kept at a high or low level and must not be left floating during the detection phase.
 - If CAN2 is used to connect to the bootloader: the USART1_RX (PA10), USART2_RX (PD6), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins have to be kept at a high or low level and must not be left floating during the detection phase.
 - If DFU is used to connect to the bootloader: the USART1_RX (PA10), USART2_RX (PD6) and CAN2_RX (PB5) pins have to be kept at a high or low level and must not be left floating during the detection phase.
- Connection to the peripheral to be performed through:
 - an RS232 serial interface (example, ST3232 RS232 transceiver) has to be directly connected to the USART1_RX (PA10) and USART1_TX (PA9) pins when USART1 is used, or to the USART2_RX (PD6) and USART2_TX (PD5) pins when USART2 is used
 - a CAN interface (CAN transceiver) has to be directly connected to the CAN2_RX (PB5) and CAN2_TX (PB6) pins
 - a certified USB cable has to be connected to the microcontroller (optionally an ESD protection circuitry can be used)

The USART1_CK, USART1_CTS and USART1_RTS pins are not used, therefore the application can use these pins for other peripherals or GPIOs. The same note is applicable for USART2.

Once the USB Device is enabled, all its related pins are dedicated to USB communication only, and cannot be used for other application purposes.

The user can control the BOOT0 and Reset pins from a PC serial applet using the RS232 serial interface which controls BOOT0 through the CTS line and Reset through the DCD line. The user must use a full null modem cable. The necessary hardware to implement for this control exists in the STM3210C-EVAL board. For more details about this, refer to document: “STM3210C-EVAL board user manual”, available from the STMicroelectronics website: <http://www.st.com>.

5.3 Bootloader selection

The STM32F105xx and STM32F107xx embedded bootloader supports four peripherals interfaces: USART1, USART2, CAN2 and DFU (USB). Any one of these peripheral interfaces can be used to communicate with the bootloader and download the application code to the internal Flash.

The embedded bootloader firmware is able to auto-detect the peripheral interface to be used. In an infinite loop, it detects any communication on the supported bootloader interfaces.

Note: *The RX pins of the peripherals not used in this bootloader must be kept at a known (low or high) level and should not be left floating during the detection phase as described below. Refer to [Section 5.2: Bootloader hardware requirements](#) for more information.*

To use the USART bootloader on USART1 or USART2, connect the serial cable to the desired interface. Once the bootloader detects the data byte 0x7F on this interface, the bootloader firmware executes the auto-baud rate sequence and then enters a loop, waiting for any USART bootloader command.

To use the CAN2 interface, connect the CAN cable to CAN2. Once the bootloader detects a frame on the CAN2_RX pin (PB5), the bootloader firmware enters a CAN loop and starts to check the external clock frequency value, if the HSE is 8 MHz, 14.7456 MHz or 25 MHz CAN bootloader firmware enters an infinite loop and waits until it receives a message, otherwise a system reset is generated.

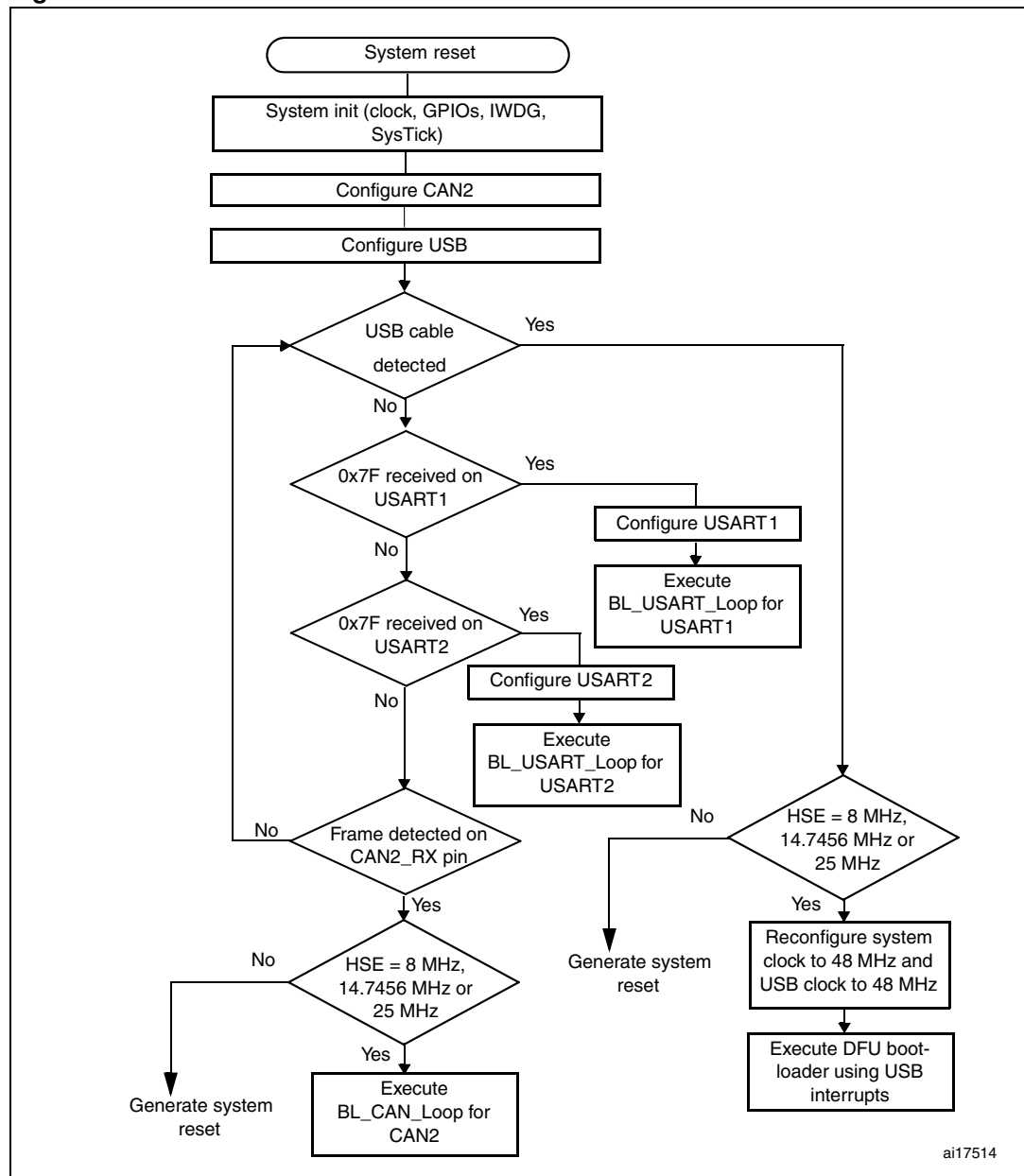
If a USB cable is plugged into the microcontroller's USB interface at any time during the bootloader firmware selection sequence, the bootloader then enters the DFU bootloader loop waiting for any DFU bootloader command.

To use the USART or the CAN bootloader, it is mandatory that no USB cable is connected to the USB peripheral during the selection phase. Once the USART or CAN bootloader is selected, the user can plug a USB cable without impacting the selected bootloader execution except commands which generate a system reset.

Once one interface is selected for the bootloader, all other interfaces are disabled.

The figure below shows the bootloader detection mechanism. More details are provided in the sections corresponding to each peripheral bootloader.

Figure 2. Bootloader selection for STM32F105xx and STM32F107xx devices



5.4 Bootloader version

The table below lists the bootloader versions and the changes between all versions of the STM32F105xx and STM32F107xx devices.

Table 7. STM32F105xx and STM32F107xx bootloader versions

Bootloader version number	Description
V1.0	Initial bootloader version.
V2.0	<ul style="list-style-type: none"> – Bootloader detection mechanism updated to fix the issue when GPIOs of unused peripherals in this bootloader are connected to low level or left floating during the detection phase. For more details please refer to Section 5.4.2. – Vector table set to 0x1FFF B000 instead of 0x0000 0000 – Go command updated (for all bootloaders): USART1, USART2, CAN2, GPIOA, GPIOB, GPIOD and SysTick peripheral registers are set to their default reset values – DFU bootloader: USB pending interrupt cleared before executing the Leave DFU command – DFU subprotocol version changed from V1.0 to V1.2 – Bootloader version updated to V2.0
V2.1	<ul style="list-style-type: none"> – Fixed PA9 excessive consumption described in Section 5.4.4. – Get-Version command (defined in AN3155) corrected. It returns 0x22 instead of 0x20 in bootloader V2.0. Refer to Section 5.4.3 for more details. – Bootloader version updated to V2.1
V2.2	<ul style="list-style-type: none"> – Fixed DFU option bytes descriptor (set to 'e' instead of 'g' because it is read/write and not erasable). – Fixed DFU polling timings for Flash Read/Write/Erase operations. – Robustness enhancements for DFU bootloader interface. – Updated Bootloader version to V2.2.

5.4.1 How to identify STM32F105xx/107xx bootloader versions

Bootloader V1.0 is implemented on devices which date code is below 937 (refer to STM32F105xx and STM32F107xx datasheet for where to find the date code on the device marking). Bootloader V2.0 and V2.1 are implemented on devices with a date code higher or equal to 937.

There are two ways to distinguish between bootloader versions:

- When using the USART bootloader, the Get-Version command defined in AN2606 and AN3155 has been corrected in V2.1 version. It returns 0x22 instead of 0x20 as in bootloader V2.0.
- The values of the vector table at the beginning of the bootloader code are different. The user software (or via JTAG/SWD) reads 0x1FFFE945 at address 0x1FFFB004 for

bootloader V2.0 0x1FFFE9A1 for bootloader V2.1, and 0x1FFFE9C1 for bootloader V2.2.

- The DFU version is the following:
 - V2.1 in Bootloader V2.1
 - V2.2 in Bootloader V2.2.

It can be read through the `bcdDevice` field of the DFU Device Descriptor.

5.4.2 Bootloader unavailability on STM32F105xx/STM32F107xx devices with a date code below 937

Description

The bootloader cannot be used if the USART1_RX (PA10), USART2_RX (PD6, remapped), CAN2_Rx (PB5, remapped), OTG_FS_DM (PA11), and/or OTG_FS_DP (PA12) pin(s) are held low or left floating during the bootloader activation phase.

The bootloader cannot be connected through CAN2 (remapped), DFU (OTG FS in Device mode), USART1 or USART2 (remapped).

On 64-pin packages, the USART2_RX signal remapped PD6 pin is not available and it is internally grounded. In this case, the bootloader cannot be used at all.

Workaround

- For 64-pin packages
 - None. The bootloader cannot be used.
- For 100-pin packages
 - Depending on the used peripheral, the pins for the unused peripherals have to be kept at a high level during the bootloader activation phase as described below:
 - If USART1 is used to connect to the bootloader, PD6 and PB5 have to be kept at a high level.
 - If USART2 is used to connect to the bootloader, PA10, PB5, PA11 and PA12 have to be kept at a high level.
 - If CAN2 is used to connect to the bootloader, PA10, PD6, PA11 and PA12 have to be kept at a high level.
 - If DFU is used to connect to the bootloader, PA10, PB5 and PD6 have to be kept at a high level.

Note: This limitation applies only to STM32F105xx and STM32F107xx devices with a date code below 937. STM32F105xx and STM32F107xx devices with a date code higher or equal to 937 are not impacted. See STM32F105xx and STM32F107xx datasheet for where to find the date code on the device marking.

5.4.3 USART bootloader Get-Version command returns 0x20 instead of 0x22

Description

In USART mode, the Get-Version command (defined in AN3155) returns 0x20 instead of 0x22.

This limitation is present on bootloader versions V1.0 and V2.0, while it is fixed in bootloader version 2.1.

Workaround

None.

5.4.4 PA9 excessive power consumption when USB cable is plugged in bootloader V2.0**Description**

When connecting an USB cable after booting from System-Memory mode, PA9 pin (connected to $V_{BUS}=5\text{ V}$) is also shared with USART TX pin which is configured as alternate push-pull and forced to 0 since the USART peripheral is not yet clocked. As a consequence, a current higher than 25 mA is drained by PA9 I/O and may affect the I/O pad reliability.

This limitation is fixed in bootloader version 2.1 by configuring PA9 as alternate function push-pull when a correct 0x7F is received on RX pin and the USART is clocked. Otherwise, PA9 is configured as alternate input floating.

Workaround

None.

6 STM32F101xx and STM32F103xx XL-density device bootloader

Throughout this section **STM32F10xxx XL-density** is used to refer to XL-density STM32F101xx and STM32F103xx devices.

6.1 Dual bank boot feature

For STM32F101xx and STM32F103xx XL-density devices (these devices have two Flash memory banks: Bank 1 and Bank 2), an additional boot mechanism is available which allows booting from Bank 2 or Bank 1 (depending on the BFB2 bit status (bit 19 in the user option bytes @ 0x1FFFF800)).

1. When the BFB2 bit is reset, and the boot pins are configured to boot from the Flash memory (BOOT0 = 0 and BOOT1 = x) then, after reset, the device boots from the System memory and executes the embedded bootloader code which implements the dual bank Boot mode:
 - a) First, the code checks Bank 2. If it contains a valid code (see [Note](#): below), it jumps to application located in Bank 2 and leaves the Bootloader.
 - b) If the Bank 2 code is not valid, it checks Bank 1 code. If it is valid (see “*note*” below), it jumps to the application located in Bank 1.
 - c) If both Bank 2 and Bank 1 do not contain valid code (see “*note*” below), the normal Bootloader operations are executed as described in the following sections (no jump to Flash banks is executed). Refer to [Figure 3: Bootloader selection for STM32F10xxx XL-density devices](#) for more details.
2. When the bit BFB2 is set (default state), the dual bank boot mechanism is not performed.

Note: *The code is considered as valid when the first data (at the bank start address, which should be the stack pointer) points to a valid address into the internal SRAM memory (stack top address). If the first address points to any other location (out of the internal SRAM) the code is considered not valid.*

A dual bank Boot mode example (FLASH\Dual_Boot) is provided within the STM32F10x Standard Peripheral Library available on <http://www.st.com>.

For the STM32F101xx and STM32F103xx XL-density devices, the Flash memory, system memory or SRAM is selected as the boot space, as shown in [Table 8](#) below.

Table 8. Boot pin and BFB2 bit configuration

BFB2 bit	Boot mode selection pins		Boot mode	Aliasing
	BOOT1	BOOT0		
1	X	0	User Flash memory	User Flash memory is selected as the boot space
	0	1	System memory	System memory is selected as the boot space
	1	1	Embedded SRAM	Embedded SRAM is selected as the boot space
0	X	0	System memory	System memory is selected as the boot space then dual bank mechanism is executed
	0	1	System memory	System memory is selected as the boot space then dual bank mechanism is executed
	1	1	Embedded SRAM	Embedded SRAM is selected as the boot space

[Table 8](#) shows that the XL-density devices enter System memory boot mode in two cases:

1. If the BOOT pins are configured as follows: BOOT0 = 1 and BOOT1 = 0
2. Or if:
 - a) the BFB2 bit is reset and
 - b) boot pins are configured as follows: BOOT0 = 0 and BOOT1 = x

Note: When conditions a, b, and c below are fulfilled, it is equivalent to configuring boot pins for system memory boot (BOOT0 = 1 and BOOT1 = 0). In this case normal Bootloader operations are executed.

- a) BFB2 bit is reset
- b) Both banks don't contain valid code
- c) Boot pins configured as follows: BOOT0 = 0 and BOOT1 = x

When the BFB2 bit is cleared, and Bank 2 and/or Bank 1 contain valid user application code, the Dual Bank Boot is always performed (bootloader always jumps to the user code and never continues normal operations).

Consequently, if you have cleared the BFB2 bit (to boot from Bank 2) then, to be able to execute the Bootloader code, you have to:

- either, set the BFB2 bit to 1

- or, program the content of address 0x0808 0000 (base address of Bank2) and 0x0800 0000 (base address of Bank1) to 0x0

6.2 Bootloader configuration

The bootloader embedded in STM32F10xxx XL-density supports two serial interfaces: USART1 and USART2.

The following table shows the required hardware resources of STM32F10xxx XL-density devices used by the bootloader in System memory boot mode.

Table 9. STM32F10xxx XL-density configuration in System memory boot mode

Feature/peripheral	State	Comment
Clock source	HSI enabled	The system clock is equal to 24 MHz using the PLL
USART1_RX pin	Input	PA10 pin: USART1 receives
USART1_TX pin	Output push-pull	PA9 pin: USART1 transmits
USART2_RX pin	Input	PD6 pin: USART2 receives (remapped pins)
USART2_TX pin	Output push-pull	PD5 pin: USART2 transmits (remapped pins)
SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host
USART1	Enabled	Once initialized the USART1/USART2 configuration is: 8-bits, even parity and 1 Stop bit.
USART2	Enabled	
RAM	-	2 Kbytes starting from address 0x2000 0000 are used by the bootloader firmware
System memory	-	6 Kbytes starting from address 0x1FFF E000, contain the bootloader firmware
IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (in case the hardware IWDG option was previously enabled by the user)

The system clock is derived from the embedded internal high-speed RC, no external quartz is required for the bootloader code.

After downloading the application binary, if you choose to execute the Go command, all peripheral registers used by the bootloader (shown in [Table 9](#)) are initialized to their default reset values before jumping to the user application.

If the user application uses the IWDG, the IWDG prescaler value has to be adapted to meet the requirements of the application (since the prescaler was set to its maximum value by the bootloader).

6.3 Bootloader hardware requirements

The hardware required to put the STM32F10xx XL-density devices into System memory boot mode consists of any circuitry, switch or jumper, capable of holding the BOOT0 pin high and the BOOT1 pin low during reset.

Note: As explained in [Section 6.1: Dual bank boot feature](#), the System memory boot mode can also be executed by software when the BFB2 bit is reset, both banks start addresses are erased, and boot pins are configured to boot from Flash memory.

To connect to the STM32F10xx XL-density devices during System memory boot mode, the following conditions have to be verified:

- The RX pin of the peripherals unused in this bootloader have to be kept at a known (low or high) level, and should not be left floating during the detection phase as described below:
 - If the USART1 is used to connect to the bootloader: the USART2_RX (PD6) pin has to be kept at a high or low level and must not be left floating during the detection phase.
 - If the USART2 is used to connect to the bootloader: the USART1_RX (PA10) pin has to be kept at a high or low level and must not be left floating during the detection phase.
- When the BFB2 bit is cleared, and Bank 2 and/or Bank 1 contain a valid user application code, the Dual Bank Boot is always performed (bootloader always jumps to the user code and never continues normal operations). Consequently, if you have cleared the BFB2 bit (to boot from Bank 2), then to be able to execute the Bootloader code, you have to:
 - either, set the BFB2 bit to 1
 - or, program the content of address 0x0808 0000 (base address of Bank2) and 0x0800 0000 (base address of Bank1) to 0x0
- Connection to the peripheral to be performed through:
 - an RS232 serial interface (example, ST3232 RS232 transceiver) has to be directly connected to the USART1_RX (PA10) and USART1_TX (PA9) pins when USART1 is used, or to the USART2_RX (PD6) and USART2_TX (PD5) pins when USART2 is used

The USART1_CK, USART1_CTS and USART1_RTS pins are not used, therefore the application can use these pins for other peripherals or GPIOs. This is also applicable for USART2.

6.4 Bootloader selection

The STM32F10xx XL-density embedded Bootloader supports two peripheral interfaces: USART1 and USART2. Any one of these peripheral interfaces can be used to communicate with the bootloader and download the application code to the internal Flash.

The embedded Bootloader firmware is able to auto-detect the peripheral interface to be used. In an infinite loop, it detects any communication on the supported bootloader interfaces.

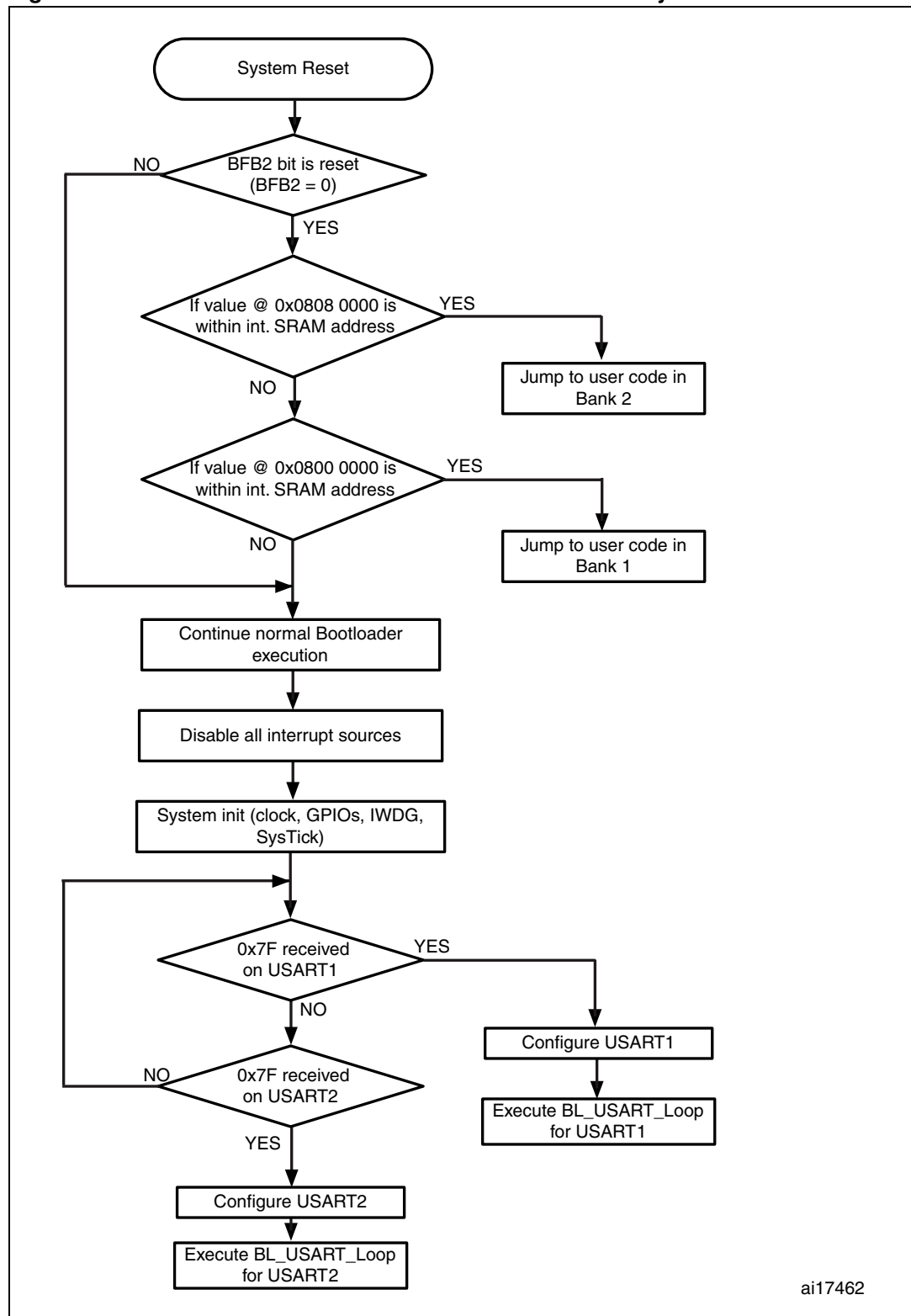
Note: *The RX pins of the peripherals not used in this bootloader must be kept at a known (low or high) level and should not be left floating during the detection phase as described below. Refer to [Section 6.3: Bootloader hardware requirements](#) for more information.*

To use the USART bootloader on USART1 or USART2, connect the serial cable to the desired interface. Once the bootloader detects the data byte 0x7F on this interface, the bootloader firmware executes the auto-baudrate sequence and then enters a loop, waiting for any USART bootloader command.

Once one interface is selected for the bootloader, the other interface is disabled.

[Figure 3](#) shows the bootloader detection mechanism. More details are provided in the sections corresponding to each peripheral bootloader.

Figure 3. Bootloader selection for STM32F10xxx XL-density devices



6.5 Bootloader version

[Table 10](#) lists the bootloader versions for the STM32F101xx and STM32F103xx XL-density devices.

Table 10. XL-density bootloader versions

Bootloader version number	Description
V2.1	Initial bootloader version

7 STM32L15xx Medium-density Ultralow power device bootloader

Through all this section **STM32L15xxx** will be used as reference to Medium-density STM32L151xx and STM32L152xx ultralow power devices.

7.1 Bootloader configuration

The bootloader embedded in STM32L15xxx devices supports two serial interfaces: USART1 and USART2 peripherals.

The following table shows the required hardware resources of STM32L15xx devices used by the bootloader in System memory boot mode.

Table 11. STM32L15xxx configuration in System memory boot mode

Feature/Peripheral	State	Comment
Clock source	HSI enabled	The system clock is equal to 16 MHz
USART1_RX pin	Input	PA10 pin: USART1 receives
USART1_TX pin	Output	PA9 pin: USART1 transmits
USART2_RX pin	Input	PD06 pin: USART2 receives
USART2_TX pin	Output	PD05 pin: USART2 transmits
SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.
USART1	Enabled	Once initialized the USART1 configuration is: 8-bits, even parity and 1 Stop bit
USART2	Enabled	Once initialized the USART2 configuration is: 8-bits, even parity and 1 Stop bit
RAM	-	2 Kbytes starting from address 0x2000 0000 are used by the bootloader firmware
System memory	-	4 Kbytes starting from address 0x1FF0 0000, contain the bootloader firmware
IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (in case the hardware IWDG option was previously enabled by the user)
Power	-	Voltage range is set to Voltage Range 2

The system clock is derived from the embedded internal high-speed RC, no external quartz is required for the bootloader code

After downloading the application binary, if you choose to execute the Go command, all peripheral registers used by the bootloader (shown in the above table) are initialized to their default reset values before jumping to the user application. If the user application uses the IWDG, the IWDG prescaler value has to be adapted to meet the requirements of the application (since the prescaler was set to its maximum value by the bootloader).

7.2 Bootloader hardware requirements

The hardware required to put the STM32L15xx devices into System memory boot mode consists of any circuitry, switch or jumper, capable of holding the BOOT0 pin high and the BOOT1 pin low during reset.

To connect to the STM32L15xx devices during System memory boot mode, the following conditions have to be verified:

- The RX pins of the peripherals unused in this bootloader have to be kept at a known (low or high) level, and should not be left floating during the detection phase as described below:
 - If USART1 is used to connect to the bootloader: the USART2_RX (PD6) pin has to be kept at a high or low level and must not be left floating during the detection phase.
 - If USART2 is used to connect to the bootloader: the USART1_RX (PA10) pin has to be kept at a high or low level and must not be left floating during the detection phase.
- The peripheral to be used has to be connected through an RS232 serial interface (example, ST3232 RS232 transceiver) which must be:
 - Directly connected to the USART1_RX (PA10) and USART1_TX (PA9) pins when USART1 is used
 - Directly connected to the USART2_RX (PD6) and USART2_TX (PD5) pins when USART2 is used

The USART1_CK, USART1_CTS and USART1_RTS pins are not used, therefore the application can use these pins for other peripherals or GPIOs. The same note is applicable for USART2.

The user can control the BOOT0 and Reset pins from a PC serial applet using the RS232 serial interface which controls BOOT0 through the CTS line and Reset through the DCD line. The user must use a full null modem cable. The necessary hardware to implement for this control exists in the STM32L152-EVAL board. For more details about this, refer to the “STM32L152-EVAL board user manual” (UM1009), available from the STMicroelectronics website: <http://www.st.com>.

7.3 Bootloader selection

The STM32L15xx devices embedded bootloader supports two peripherals interfaces: USART1 and USART2. Any one of these peripheral interfaces can be used to communicate with the bootloader and download the application code to the internal Flash.

The embedded bootloader firmware is able to auto-detect the peripheral interface to be used. In an infinite loop, it detects any communication on the supported bootloader interfaces.

Note: *The RX pins of the peripherals not used in this bootloader must be kept at a known (low or high) level and should not be left floating during the detection phase as described below. Refer to [Section 7.2: Bootloader hardware requirements](#) for more information.*

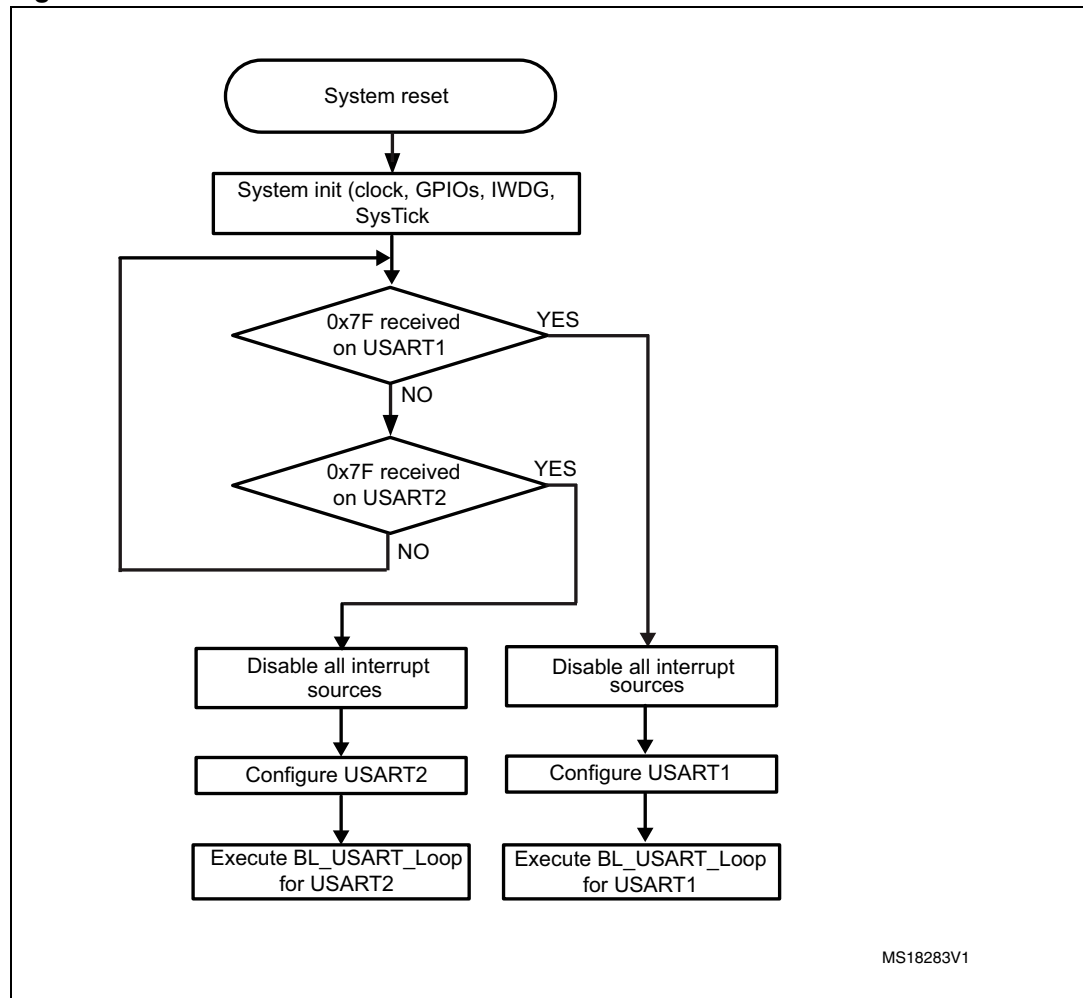
To use the USART bootloader on USART1 or USART2, connect the serial cable to the desired interface. Once the bootloader detects the data byte 0x7F on this interface, the

bootloader firmware executes the autobaudrate sequence and then enters a loop, waiting for any USART bootloader command.

Once one interface is selected for the bootloader, the other interface is disabled.

The figure below shows the bootloader detection mechanism. More details are provided in the sections corresponding to each peripheral bootloader.

Figure 4. Bootloader selection for STM32L15xxx devices



7.4 Important considerations

The bootloader of the Medium-density ultralow power devices has some specific features that should be taken into consideration, as described below:

- In addition to standard memories (internal Flash, internal SRAM, option bytes and System memory), the STM32L15xxx device bootloader firmware supports Data Memory (4 Kbytes from 0x08080000 to 0x08080FFF). Refer to the PM0062 Programming manual for more information.
- **Flash memory write** operations are performed through a program memory half page write operation. The bootloader firmware manages half page write operations at non-aligned addresses. Consequently, all write operations must only be Word-aligned (the address should be a multiple of 4). The number of data to be written must also be a multiple of 4 (non-aligned half page write addresses are accepted). Be aware of the duration needed for a write operation by referring to the product datasheet.
- **Data memory** can be read and written but cannot be erased using the Erase Command. When writing in a Data memory location, the bootloader firmware manages the erase operation of this location before any write. A write to Data memory must be Word-aligned (address to be written should be a multiple of 4) and the number of data must also be a multiple of 4. To erase a Data memory location, you can write zeros at this location.
- **Option byte**
Address is 0x1FF80000. They allow three levels of protection:
 - Level 0
 - Level 1
 - Level 2Refer to PM0062 programming manual for more details about protection levels.
- **Read protect** command corresponds to the Level 1 protection.
- **Read unprotect** command corresponds to the Level 0 protection.
- **Mass erase** command is not supported by STM32L15xxx device Bootloader firmware. To perform a mass erase operation, two options are available:
 - Erase all sectors one by one using the Erase command
 - Set protection level to Level 1. Then, set it to Level 0 (using the Read protect command and then the Read Unprotect command). This operation results in a mass erase of the internal Flash memory (refer to Programming Manual PM0062 for more details).

7.5 Bootloader version

The following table lists the STM32L15xxx bootloader versions.

Table 12. STM32L15xxx bootloader versions

Bootloader version number	Description	Known limitations
V2.0	Initial bootloader version.	When a Read Memory command or Write Memory command is issued with an unsupported memory address and a correct address checksum (ie. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next 2 bytes (which are the number of bytes to be read/written and its checksum) are considered as a new command and its checksum. ⁽¹⁾

1. If the “number of data - 1” (N-1) to be read/written is not equal to a valid command code (0x00, 0x01, 0x02, 0x11, 0x21, 0x31, 0x43, 0x44, 0x63, 0x73, 0x82 or 0x92), then the limitation is not perceived from the host since the command is NACKed anyway (as an unsupported new command).

8 STM32L15xx and STM32L16xx High-density ultralow power device bootloader

Throughout this section, STM32L1xx High-density is used to refer to STM32L15xx and STM32L16xx High-density ultralow power devices.

8.1 Dual bank boot feature

The STM32L1xx High-density devices have two Flash memory banks: Bank 1 and Bank 2. They feature an additional boot mechanism which allows booting from Bank 2 or Bank 1 depending on BFB2 bit status (bit 7 in the user option bytes located at 0x1FF8 0004).

- When the BFB2 bit is reset and the boot pins are configured to boot from Flash memory (BOOT0 = 0 and BOOT1 = x), after reset the device boots from the System memory and executes the embedded bootloader code which implements the dual bank Boot mode:
 - a) The code first checks Bank 2. If it contains a valid code (see note below), it jumps to the application code located in Bank 2 and leaves the Bootloader.
 - b) If the Bank 2 code is not valid, it checks Bank 1 code. If it is valid (see note below), it jumps to the application located in Bank 1.
 - c) If both Bank 2 and Bank 1 do not contain valid code (see note below), the normal Bootloader operations are executed as described in the following sections and no jump to Flash banks is performed. Refer to [Figure 5: Bootloader selection for STM32L1xx High-density devices](#) for more details.
- 3. When BFB2 bit is set (default state), the dual bank boot mechanism is not performed.

Note: *The code is considered as valid when the first data (at the bank start address, which should be the stack pointer) points to a valid address into the internal SRAM memory (stack top address). If the first address points to any other location (out of the internal SRAM) the code is considered not valid.*

A dual bank Boot mode example (FLASH\Dual_Boot) is provided within the STM32L1xx Standard Peripheral Library available from <http://www.st.com>.

For the STM32L1xx High-density devices, the Flash memory, system memory or SRAM is selected as the boot space, as shown in [Table 13](#) below.

Table 13. Boot pin and BFB2 bit configuration

BFB2 bit	Boot mode selection pins		Protection level2	Bank2 Valid	Bank1 Valid	Boot mode	Aliasing
	BOOT1	BOOT0					
1	X	0	X	X	X	User Flash memory	User Flash memory Bank1 is selected as the boot space
	0	1	No	X	X	System memory	System memory is selected as the boot space
	0	1	Yes	X	X	User Flash memory	User Flash memory Bank1 is selected as the boot space
	1	1	No	X	X	Embedded SRAM	Embedded SRAM is selected as the boot space
	1	1	Yes	X	X	User Flash memory	User Flash memory Bank1 is selected as the boot space
0	X	0	X	Yes	X	System memory	User Flash memory Bank2 is selected as the boot space
				No	Yes	System memory	User Flash memory Bank1 is selected as the boot space
			No	No	No	System memory	System memory is selected as the boot space
			Yes	No	No	System memory	CPU blocked (halted)
	0	1	No	X	X	System memory	System memory is selected as the boot space
	1	1	No	X	X	Embedded SRAM	Embedded SRAM is selected as the boot space
	X	1	Yes	Yes	X	System memory	User Flash memory Bank2 is selected as the boot space
				No	Yes	System memory	User Flash memory Bank1 is selected as the boot space
				No	No	System memory	CPU blocked (halted)

[Table 13](#) shows that the STM32L1xx High-density devices enter System memory boot mode in two cases:

- If the BOOT pins are configured as follows:
BOOT0 = 1 and BOOT1 = 0
- If the BFB2 bit is reset and protection Level2 is enabled
- If the BFB2 bit is reset and boot pins are configured as follows:
BOOT0 = 0 and BOOT1 = x

Note: When the conditions a, b, and c described below are fulfilled, it is equivalent to configuring boot pins for system memory boot (BOOT0 = 1 and BOOT1 = 0). In this case normal Bootloader operations are executed.

- a) BFB2 bit is reset*
- b) Both banks don't contain valid code*
- c) Boot pins configured as follows: BOOT0 = 0 and BOOT1 = x*

When the BFB2 bit is cleared, and Bank 2 and/or Bank 1 contain valid user application code, the Dual Bank Boot is always performed (bootloader always jumps to the user code and never continues normal operations).

Consequently, if you have cleared the BFB2 bit (to boot from Bank 2) then, to be able to execute the Bootloader code, you have to:

- either, set the BFB2 bit to 1*
- or, program the content of address 0x0803 0000 (base address of Bank2) and 0x0800 0000 (base address of Bank1) to 0x0.*

8.2 Bootloader configuration

The bootloader embedded in STM32L1xx High-density devices supports three serial interfaces: USART1, USART2 and DFU (USB)

The following table shows the required hardware resources of STM32L1xx High-density devices used by the bootloader in System memory boot mode.

Table 14. STM32L1xx High-density configuration in System memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 16 MHz using the HSI. This is used only for USART1 and USART2 bootloaders and during USB detection for DFU bootloader (once the DFU bootloader is selected, the clock source will be derived from the external crystal).
		HSE enabled	The external clock is mandatory only for DFU bootloader and it must be in the following range: [24, 16, 12, 8, 6, 4, 3, 2] MHz. The PLL is used to generate the USB 48 MHz clock and the 32 MHz clock for the system clock.
		-	The clock security system (CSS) interrupt is enabled for the DFU bootloader. Any failure (or removal) of the external clock generates system reset.
	IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (in case the hardware IWDG option was previously enabled by the user).
	Power		Voltage range is set to Voltage Range 2
	System memory	-	8 Kbytes starting from address 0x1FF0 0000. This area contains the bootloader firmware
	RAM	-	4 Kbytes starting from address 0x2000 0000 are used by the bootloader firmware.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is: 8-bits, even parity and 1 Stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode.
	USART2_RX (PD6), USB_DM (PA11) and USB_DP (PA12) pins must be kept at a high or low level during the detection phase.		
USART1 and USART2 bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.

Table 14. STM32L1xx High-density configuration in System memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is: 8-bits, even parity and 1 Stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode.
	USART1_RX (PA10), USB_DM (PA11) and USB_DP (PA12) pins must be kept at a high or low level during the detection phase.		
DFU bootloader	USB_DM pin	Input or alternate function, automatically controlled by the USB	PA11: USB Send-Receive data line
	USB_DP pin		PA12: USB Send-Receive data line
	Interrupts	Enabled	USB Low Priority interrupt vector is enabled and used for USB DFU communication.
	USART1_RX (PA10) and USART2_RX (PD6) pins must be kept at a high or low level during the detection phase.		

Note: *For DFU interface, the external clock source (HSE) is required for USB operations. The detection of the HSE value is done by the Bootloader firmware and is based on the internal oscillator clock (HSI, MSI). Thus, when due to temperature or other conditions, the internal oscillator precision is altered above the tolerance band (1% around theoretical value), the Bootloader might calculate a wrong HSE frequency value. In this case, the Bootloader DFU interface might dysfunction or might not work at all.*

The system clock is derived from the embedded internal high-speed RC for USARTx bootloader. This internal clock is used also for DFU bootloader but only for the selection phase. An external clock in the range of [24, 16, 12, 8, 6, 4, 3, 2] MHz is required for DFU bootloader execution after the selection phase.

After downloading the application binary, if you choose to execute the Go command, all peripheral registers used by the bootloader (shown in the above table) are initialized to their default reset values before jumping to the user application.

If the user application uses the IWDG, the IWDG prescaler value has to be adapted to meet the requirements of the application (since the prescaler was set to its maximum value by the bootloader).

8.3 Bootloader hardware requirements

The hardware required to put the STM32L1xx High-density devices into System memory boot mode consists of any circuitry, switch or jumper, capable of holding the BOOT0 pin high and the BOOT1 pin low during reset.

Note: As explained in [Section 8.1: Dual bank boot feature](#), the System memory boot mode can also be executed by software when the BFB2 bit is reset, both banks start addresses are erased, and boot pins are configured to boot from Flash memory.

To connect to the STM32L1xx High-density devices during System memory boot mode, the following conditions have to be verified:

- The RX pin of the peripherals that are not used in this bootloader have to be kept at a known (low or high) level, and should not be left floating during the detection phase as described below:
 - If USART1 is used to connect to the bootloader: the USART2_RX (PD6), USB_DM (PA11) and USB_DP (PA12) pins have to be kept at a high or low level and must not be left floating during the detection phase.
 - If USART2 is used to connect to the bootloader: the USART1_RX (PA10), USB_DM (PA11) and USB_DP (PA12) pins have to be kept at a high or low level and must not be left floating during the detection phase.
 - If DFU (USB) is used to connect to the bootloader: the USART1_RX (PA10) and USART2_RX (PD6) pins have to be kept at a high or low level and must not be left floating during the detection phase.
- When the BFB2 bit is cleared, and Bank 2 and/or Bank 1 contain a valid user application code, the Dual Bank Boot is always performed (bootloader always jumps to the user code and never continues normal operations). Consequently, if you have cleared the BFB2 bit (to boot from Bank 2), then to be able to execute the Bootloader code, you have to:
 - either, set the BFB2 bit to 1
 - or, program the content of address 0x0803 0000 (base address of Bank2) and 0x0800 0000 (base address of Bank1) to 0x0
- Connection to the peripheral to be performed through:
 - an RS232 serial interface (example, ST3232 RS232 transceiver) has to be directly connected to the USART1_RX (PA10) and USART1_TX (PA9) pins when USART1 is used, or to the USART2_RX (PD6) and USART2_TX (PD5) pins when USART2 is used
 - A certified USB cable has to be connected to the microcontroller (optionally an ESD protection circuitry can be used).

The USART1_CK, USART1_CTS and USART1_RTS pins are not used. as a result, the application can use these pins for other peripherals or GPIOs. This is also applicable for USART2.

8.4 Bootloader selection

STM32L1xx High-density embedded Bootloader supports three serial interfaces: USART1, USART2 and DFU (USB). Any one of these peripheral interfaces can be used to communicate with the bootloader and download the application code to the internal Flash.

The embedded Bootloader firmware is able to auto-detect the peripheral interface to be used. In an infinite loop, it detects any communication on the supported bootloader interfaces.

Note: *The RX pins of the peripherals not used in this bootloader must be kept at a known (low or high) level and should not be left floating during the detection phase as described below. Refer to [Section 8.3: Bootloader hardware requirements](#) for more information.*

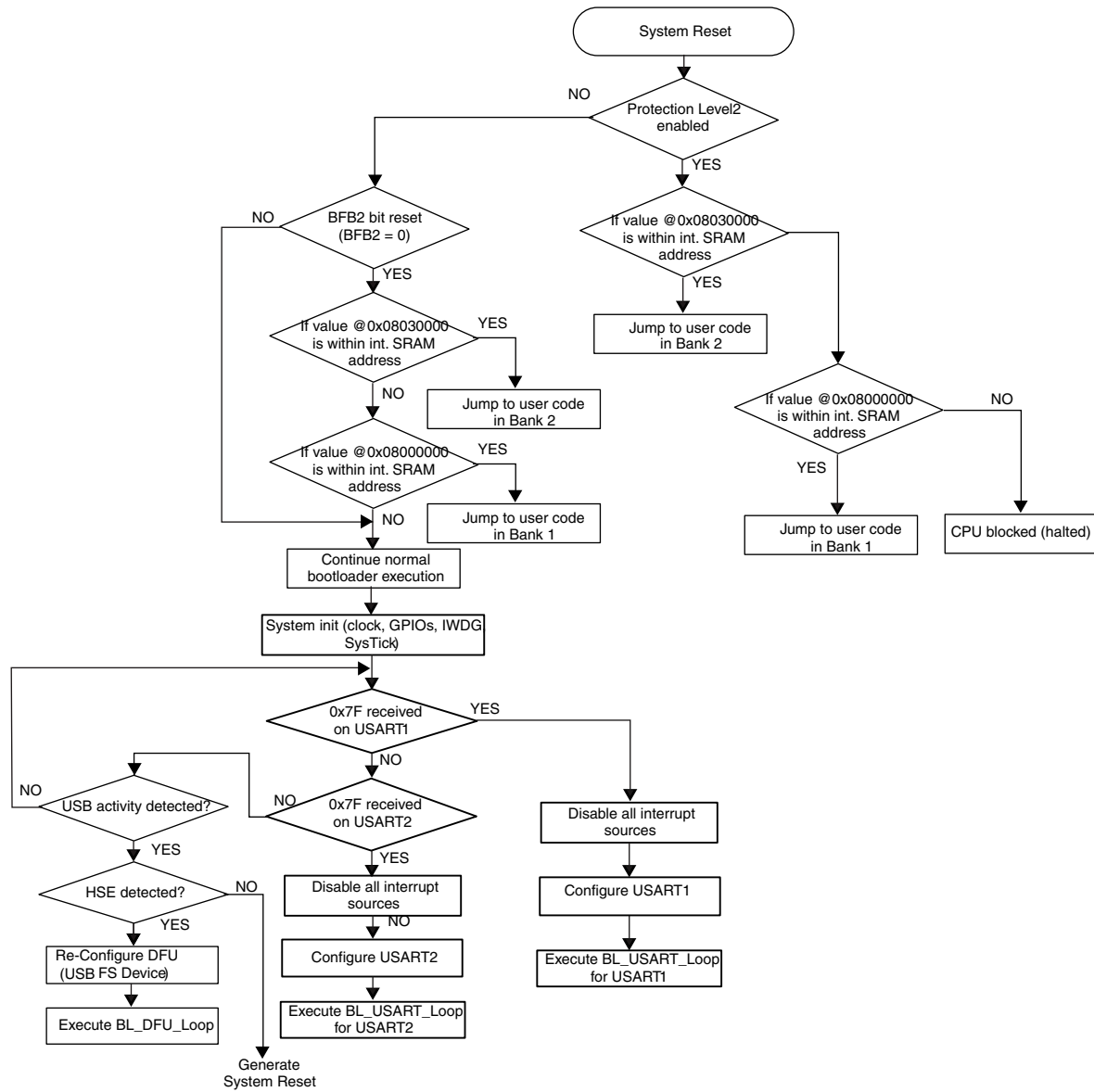
To use the USART bootloader on USART1 or USART2, connect the serial cable to the desired interface. Once the bootloader detects the data byte 0x7F on this interface, the bootloader firmware executes the auto-baudrate sequence and then enters a loop, waiting for any USART bootloader command.

If a USB cable is plugged into the microcontroller into USB interface at any time during the bootloader firmware selection sequence, the bootloader enters DFU bootloader loop waiting for any DFU bootloader command.

To use the USART bootloader, it is mandatory that no USB Host is connected to the USB peripheral during the selection phase. Once the USART bootloader is selected, the user can plug a USB cable without impacting the selected bootloader execution except for the commands which generate a system reset.

Once an interface is selected for the bootloader, the other interface is disabled.

[Figure 5: Bootloader selection for STM32L1xx High-density devices](#) shows the bootloader detection mechanism. More details are provided in the sections corresponding to each peripheral bootloader.

Figure 5. Bootloader selection for STM32L1xx High-density devices


MS30418V1

8.5 Important considerations

The bootloader of the STM32L1xx High-density devices has some specific features that should be taken into consideration, as described below:

- In addition to standard memories (internal Flash, internal SRAM, option bytes and System memory), the STM32L1xx High-density devices bootloader firmware supports Data Memory (12 Kbytes from 0x08080000 to 0x08082FFF). Refer to the PM0062 Programming manual for more information.
- **Flash memory write** operations are performed through a program memory half page write operation. The bootloader firmware manages half page write operations at non-aligned addresses. Consequently, all write operations must only be Word-aligned (the address should be a multiple of 4). The number of data to be written must also be a multiple of 4 (non-aligned half page write addresses are accepted). Be aware of the duration needed for a write operation by referring to the product datasheet.
- **Data memory** can be read and written but cannot be erased using the Erase Command. When writing in a Data memory location, the bootloader firmware manages the erase operation of this location before any write. A write to Data memory must be Word-aligned (address to be written should be a multiple of 4) and the number of data must also be a multiple of 4. To erase a Data memory location, you can write zeros at this location.
- **Option byte**
Address is 0x1FF80000. They allow three levels of protection:
 - Level 0
 - Level 1
 - Level 2Refer to PM0062 programming manual for more details about protection levels.
- **Read protect** command corresponds to the Level 1 protection.
- **Read unprotect** command corresponds to the Level 0 protection.
- **Mass erase** command is not supported by STM32L1xx High-density devices Bootloader firmware. To perform a mass erase operation, two options are available:
 - Erase all sectors one by one using the Erase command
 - Set protection level to Level 1. Then, set it to Level 0 (using the Read protect command and then the Read Unprotect command). This operation results in a mass erase of the internal Flash memory (refer to Programming Manual PM0062 for more details).

8.6 Bootloader version

[Table 15](#) lists the bootloader versions for the STM32L1xx High-density devices.

Table 15. STM32L1xx High-density bootloader versions

Bootloader version number	Description	Known limitations
V4.1	Initial bootloader version	<ul style="list-style-type: none"> – In the Bootloader code the PA13 (JTMS/SWDIO) I/O output speed is configured to 400 KHz, as consequence some debugger can not connect to the device in Serial Wire mode when the Bootloader is running. – When the DFU Bootloader is selected, the RTC is reset and thus all RTC information (calendar, alarm, ...) will be lost including backup registers. Note: When the USART bootloader is selected there is no change on the RTC configuration (including backup registers).
V4.2	Fix V4.1 limitations (available on Rev.Z devices only.)	<ul style="list-style-type: none"> – Stack overflow by 8 bytes when jumping to Bank1/Bank2 if BFB2=0 or when Read Protection level is set to 2. Workaround: the user code should force in the startup file the top of stack address before to jump to the main program. This can be done in the "Reset_Handler" routine. – When the Stack of the user code is placed outside the SRAM (ie. @ 0x2000C000) the Bootloader cannot jump to that user code which is considered invalid. This might happen when using compilers which place the stack at a non-physical address at the top of the SRAM (ie. @ 0x2000C000). Workaround: place manually the stack at a physical address.
V4.5	Fix V4.2 limitations. DFU interface robustness enhancements (available on Rev.Y devices only).	None

9 STM32F205/215xx, and STM32F207/217xx bootloader

Through all this section **STM32F2xx** will be used as reference to STM32F205xx, STM32F207xx, STM32F215xx and STM32F217xx devices.

Two bootloader versions are available on STM32F2xx devices:

- V2.0 supporting USART1 and USART3
This version is embedded in STM32F2xx devices revision B.
- V3.2 supporting USART1, USART3, CAN2 and DFU (USB FS Device)
This version is embedded in STM32F2xx devices revision Y.

9.1 Bootloader V2.x

9.1.1 Bootloader configuration

The bootloader V2.x embedded in STM32F2xx devices support two serial interfaces: USART1 and USART3 peripherals.

The following table shows the required hardware resources of STM32 devices used by the bootloader V2.x in System memory boot mode.

Table 16. STM32F2xx configuration in System memory boot mode

Feature/Peripheral	State	Comment
Clock source	HSI enabled	The system clock is equal to 24 MHz
USART1_RX pin	Input	PA10 pin: USART1 receives
USART1_TX pin	Output	PA9 pin: USART1 transmits
USART3_RX pin	Input	PC11 pin: USART3 receives
USART3_TX pin	Output	PC10pin: USART3 transmits
USART3_RX pin	Input	PB11 pin: USART3 receives
USART3_TX pin	Output	PB10pin: USART3 transmits
SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.
USART1	Enabled	Once initialized the USART1 configuration is: 8-bits, even parity and 1 Stop bit
USART3	Enabled	Once initialized the USART3 configuration is: 8-bits, even parity and 1 Stop bit
RAM	-	8 Kbytes starting from address 0x2000 0000
System memory	-	30688 bytes starting from address 0x1FFF 0000 contain the bootloader firmware

Table 16. STM32F2xx configuration in System memory boot mode (continued)

Feature/Peripheral	State	Comment
IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (in case the hardware IWDG option was previously enabled by the user)
Power	-	Voltage range is set to Voltage Range: [1.62V, 2.1V] (voltage range can be configured in run time using bootloader commands. Note that in this range internal Flash write operations are allowed only in byte format (Half-Word, Word and Double-Word operations are not allowed).

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader code.

After downloading the application binary, if you choose to execute the Go command, the peripheral registers used by the bootloader (shown in the above table) are not initialized to their default reset values before jumping to the user application. They should be reconfigured in the user application if they are used. So, if the IWDG is being used in the application, the IWDG prescaler value has to be adapted to meet the requirements of the application (since the prescaler was set to its maximum value by the bootloader).

9.1.2 Bootloader hardware requirements

The hardware required to put the STM32F2xx into System memory boot mode consists of any circuitry, switch or jumper, capable of holding the BOOT0 pin high and the BOOT1 pin low during reset.

To connect to the STM32F2xx during System memory boot mode, the following conditions have to be verified:

- The RX pins of the peripherals unused in this bootloader have to be kept at a known (low or high) level, and should not be left floating during the detection phase as described below:
 - If USART1 is used to connect to the bootloader: the USART3_RX (PC11 and PB11) pins have to be kept at a high or low level and must not be left floating during the detection phase.
 - If USART3 (on PB10/PB11) is used to connect to the bootloader: the USART1_RX (PA10) and the other USART3_RX pin (PC11) have to be kept at a high or low level and must not be left floating during the detection phase.
 - If USART3 (on PC10/PC11) is used to connect to the bootloader: the USART1_RX (PA10) and the other USART3_RX pin (PB11) have to be kept at a high or low level and must not be left floating during the detection phase.
- Connection to the peripheral to be performed through:
 - An RS232 serial interface (example, ST3232 RS232 transceiver) has to be directly connected to the USART1_RX (PA10) and USART1_TX (PA9) pins when USART1 is used, or to the USART3_RX (PB11 or PC11) and USART3_TX (PB10 or PC10) pins or when USART3 is used.

The USART1_CK, USART1_CTS and USART1_RTS pins are not used, therefore the application can use these pins for other peripherals or GPIOs. The same note is applicable for USART3.

The user can control the BOOT0 and Reset pins from a PC serial applet using the RS232 serial interface which controls BOOT0 through the CTS line and Reset through the DCD line. The user must use a full null modem cable. The necessary hardware to implement for this control exists in the STM322xG-EVAL board. For more details, refer to the STM322xG-EVAL board user manual, available from the STMicroelectronics website: <http://www.st.com>.

9.1.3 Bootloader selection

The STM32F2xx embedded bootloader V2.x supports two peripheral interfaces: USART1 and USART3 (on PB10/PB11 and PC10/PC11). Any one of these peripheral interfaces can be used to communicate with the bootloader and download the application code to the internal Flash memory.

The embedded bootloader firmware is able to auto-detect the peripheral interface to be used. In an infinite loop, it detects any communication on the supported bootloader interfaces.

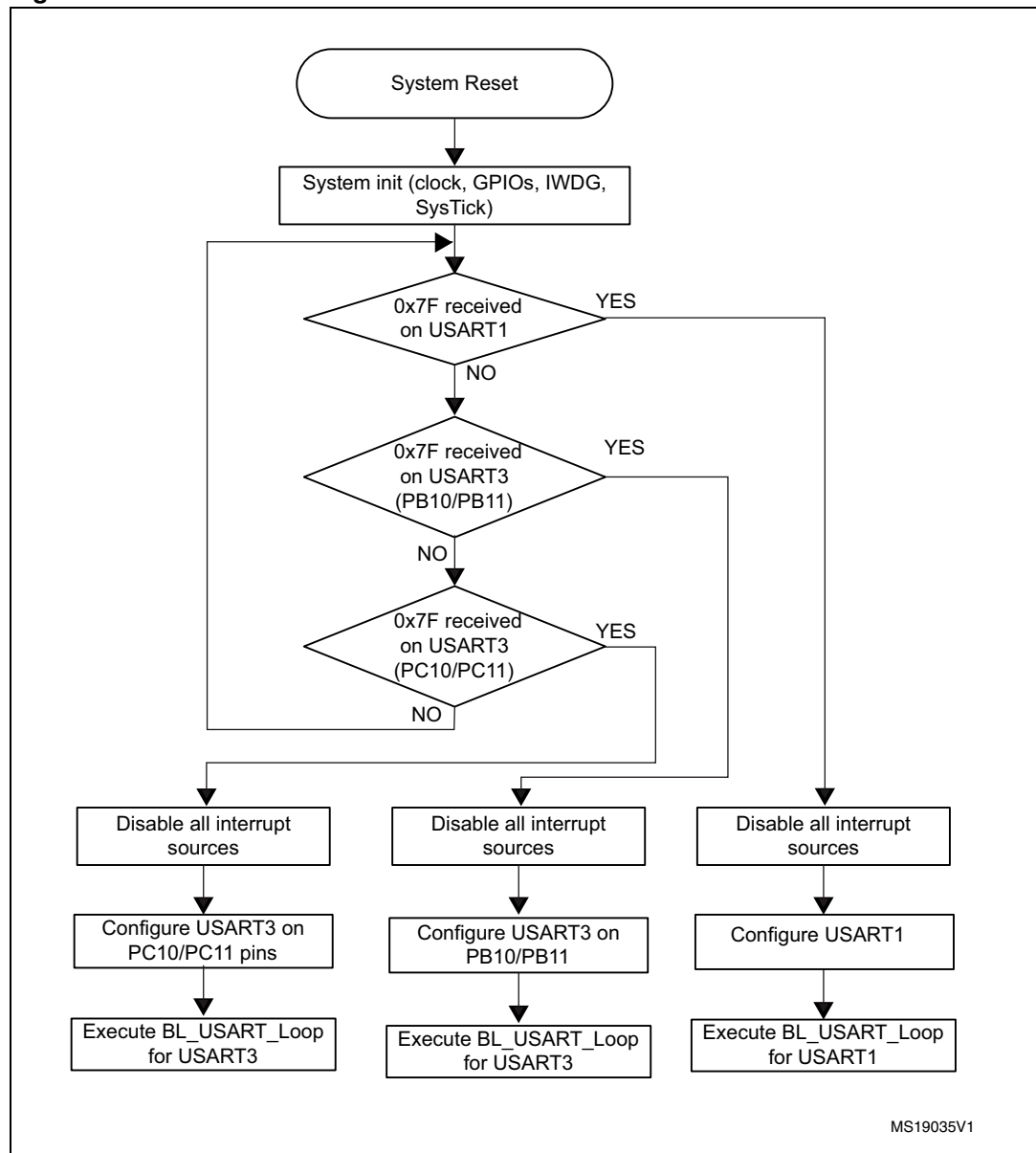
Note: *The RX pins of the peripherals not used in this bootloader must be kept at a known (low or high) level and should not be left floating during the detection phase as described below. Refer to [Section 9.1.2: Bootloader hardware requirements](#) for more information.*

To use the USART bootloader on USART1 or USART3, connect the serial cable to the desired interface. Once the bootloader detects the data byte 0x7F on this interface, the bootloader firmware executes the autobaudrate detection sequence and enters a loop, waiting for any USART bootloader command.

Once an interface is selected for the bootloader, the other interfaces are disabled.

[Figure 6](#) shows the bootloader detection mechanism. More details are provided in the sections corresponding to each peripheral bootloader.

Figure 6. Bootloader V2.x selection for STM32F2xx



9.1.4 Important considerations

The STM32F2xx bootloader has some specific features that should be taken into consideration:

- In addition to standard memories (internal Flash, internal SRAM, option bytes and System memory), STM32F2xx bootloader firmware supports OTP memory (512 bytes from 0x1FFF 7800 to 0x1FFF 7A00). Refer to PM0059 Flash programming manual for more information.
- **OTP memory** can be read and written but cannot be erased using the Erase command. When writing in an OTP memory location, make sure that the relative protection bit (in the last 16 bytes of the OTP memory) is not reset.

- **Option bytes**

Address is 0x1FFFC000. They allow three levels of protection:

- Level 0
- Level 1
- Level 2

Refer to PM0059 programming manual for more details about protection levels.

- **Read protect** command corresponds to Level 1 protection.
- **Read unprotect** command corresponds to Level 0 protection.
- **Mass erase** command on STM32F2xx takes longer than on other STM32F devices due to their memory density. Make sure that the timeout used by your host interface to wait for an acknowledge event after sending a Mass erase command is sufficient.
- **Voltage Range configuration**

The Voltage Range can be updated on the fly by the bootloader software. The Voltage Range is set to its default value at each bootloader software startup (after system reset or jump to the bootloader code). The bootloader software allows modifying this parameter through a virtual memory location. This memory location is not physical but can be read and written using usual bootloader read/write operations according to the protocol in use (USART, CAN or DFU). This memory location contains 4 bytes which are described in [Table 17](#). It can be accessed by 1, 2, 3 or 4 bytes. However, reserved bytes should remain at their default values (0xFF), otherwise the request will be NACKed.

Table 17. STM32F2xx Voltage Range configuration using bootloader V2.x

Address	Size	Description
0xFFFF0000	1 byte	This byte controls the current value of Voltage Range: 0x00: Voltage Range [1.62V, 2.1V] 0x01: Voltage Range [2.1V, 2.4V] 0x02: Voltage Range [2.4V, 2.7V] 0x03: Voltage Range [2.7V, 3.6V] 0x04: Voltage Range [2.7V, 3.6V] and Double Word write/erase operation is used. In this case it is mandatory to supply 9 V through VPP pin (refer to PM0059 for more details about Double-Word write operation). Other: all other values are not supported and will be NACKed.
0xFFFF0001	1 byte	Reserved. 0xFF: Default value. Other: all other values are not supported and will be NACKed.
0xFFFF0002	1 byte	Reserved. 0xFF: Default value. Other: all other values are not supported and will be NACKed.
0xFFFF0003	1 byte	Reserved. 0xFF: Default value. Other: all other values are not supported and will be NACKed.

9.1.5 Bootloader V2.x versions

[Table 17](#) lists the V2.x versions of STM32F2xx bootloader.

Table 18. STM32F2xx bootloader V2.x versions

Bootloader version number	Description	Known limitations
V2.0	Initial V2.x bootloader version.	When a Read Memory command or Write Memory command is issued with an unsupported memory address and a correct address checksum (ie. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next 2 bytes (which are the number of bytes to be read/written and its checksum) are considered as a new command and its checksum. ⁽¹⁾

1. If the "number of data - 1" (N-1) to be read/written is not equal to a valid command code (0x00, 0x01, 0x02, 0x11, 0x21, 0x31, 0x43, 0x44, 0x63, 0x73, 0x82 or 0x92), then the limitation is not perceived from the host since the command is NACKed anyway (as an unsupported new command).

9.2 Bootloader V3.x

9.2.1 Bootloader configuration

The bootloader V3.x embedded in STM32F2xx devices support four serial peripherals: USART1, USART3, CAN2, and DFU (USB FS Device).

[Table 19](#) shows the required hardware resources of STM32F2xx devices used by the bootloader V3.x in System memory boot mode.

Table 19. STM32F2xx configuration in System memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock is equal to 24 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USARTx interfaces are selected (once CAN or DFU bootloader is selected, the clock source will be derived from external crystal).
		HSE enabled	The system clock is equal to 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS Device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The Clock Security System (CSS) interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	8 Kbytes starting from address 0x2000 0000 are used by the bootloader firmware
	System memory	-	30688 bytes starting from address 0x1FF0 0000, contain the bootloader firmware
	IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (in case the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62V, 2.1V]. The voltage range can be configured in run time using bootloader commands. Note that in this range internal Flash write operations are allowed only in byte format (Half-Word, Word and Double-Word operations are not allowed).

Table 19. STM32F2xx configuration in System memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1 Bootloader	USART1	Enabled	Once initialized the USART1 configuration is: 8-bits, even parity and 1 Stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode
	USART3_RX (PB11), USART3_RX (PC11), CAN2_RX (PB05), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins must be kept at a high or low level during the detection phase.		
USART3 Bootloader (on PB10/PB11)	USART3	Enabled	Once initialized the USART3 configuration is: 8-bits, even parity and 1 Stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode
	USART3_TX pin	Output	PB10pin: USART3 in transmission mode
	USART1_RX (PA10), USART3_RX (PC11), CAN2_RX (PB05), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins must be kept at a high or low level during the detection phase.		
USART3 Bootloader (on PC10/PC11)	USART3	Enabled	Once initialized the USART3 configuration is: 8-bits, even parity and 1 Stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode
	USART3_TX pin	Output	PC10pin: USART3 in transmission mode
	USART1_RX (PA10), USART3_RX (PB11), CAN2_RX (PB05), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins must be kept at a high or low level during the detection phase.		
USART1 and USART3 Bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because STM32F2xx CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB05 pin: CAN2 in reception mode
	CAN2_TX pin	Output	PB13pin: CAN2 in transmission mode
	USART1_RX (PA10), USART3_RX (PB11), USART3_RX (PC11), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins must be kept at a high or low level during the detection phase.		
DFU bootloader	USB_OTG_FS	Enabled	USB OTG FS configured in Forced Device mode. USB_OTG_FS interrupt vector is enabled and used for USB DFU communications.
	USB_OTG_FS_DM pin	Input	PA11 pin: USB OTG FS DM line
	USB_OTG_FS_DP pin	Output	PA12pin: USB OTG FS DP line
	USART1_RX (PA10), USART3_RX (PB11), USART3_RX (PC11) and CAN2_RX (PB05) pins must be kept at a high or low level during the detection phase.		
CAN2 and DFU bootloaders	TIM11	Enabled	This timer is used to determine the value of the external clock frequency. Once the external clock frequency is determined, the RCC system is configured to operate at 60 MHz system clock (using PLL).

Note: *For DFU interface, the external clock source (HSE) is required for USB operations. The detection of the HSE value is done by the Bootloader firmware and is based on the internal oscillator clock (HSI). Thus, when due to temperature or other conditions, the internal oscillator precision is altered above the tolerance band (1% around theoretical value), the Bootloader might calculate a wrong HSE frequency value. In this case, the Bootloader DFU interface might dysfunction or might not work at all.*

The system clock is derived from the embedded internal high-speed RC for USARTx bootloaders. No external quartz is required in this case for the bootloader code. This internal clock is also used for CAN and DFU (USB FS Device) but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

The CAN and DFU bootloaders implement an external clock detection mechanism allowing to determine the value of the external clock using the internal high-speed RC and TIM11 timer. The accuracy of this mechanism allows to detect only frequencies multiple of 1 MHz and ranging from 4 to 26 MHz. Any other value is not supported and will result in unexpected behavior of the bootloader.

After downloading the application binary, if you choose to execute the Go command, the peripheral registers used by the bootloader (shown in the above table) are not initialized to their default reset values before jumping to the user application. They should be reconfigured in the user application if they are used. So, if the IWDG is being used in the application, the IWDG prescaler value has to be adapted to meet the requirements of the application (since the prescaler was set to its maximum value by the bootloader).

9.2.2 Bootloader hardware requirements

The hardware required to put the STM32F2xx into System memory boot mode consists of any circuitry, switch or jumper, capable of holding the BOOT0 pin high and the BOOT1 pin low during reset.

To connect to the STM32F2xx during System memory boot mode, the following conditions have to be verified:

- The RX pins of the peripheral unused in this bootloader have to be kept at a known (low or high) level, and should not be left floating during the detection phase as described below:
 - If USART1 is used to connect to the bootloader: the USART3_RX (PC11 and PB11), CAN2_RX (PB05), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins have to be kept at a high or low level and must not be left floating during the detection phase.
 - If USART3 (on PB10/PB11) is used to connect to the bootloader: the USART1_RX (PA10), USART3_RX (PC11), CAN2_RX (PB05), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) have to be kept at a high or low level and must not be left floating during the detection phase.
 - If USART3 (on PC10/PC11) is used to connect to the bootloader: the USART1_RX (PA10), USART3_RX pin (PB11), CAN2_RX (PB05), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) have to be kept at a high or low level and must not be left floating during the detection phase.
 - If CAN2 is used to connect to the bootloader: the USART1_RX (PA10), USART3_RX (PC11 and PB11), OTG_FS_DM (PA11) and OTG_FS_DP (PA12)

pins have to be kept at a high or low level and must not be left floating during the detection phase.

- If DFU (USB FS Device) is used to connect to the bootloader: the USART1_RX (PA10), USART3_RX (PC11 and PB11) and CAN2_RX (PB05) pins have to be kept at a high or low level and must not be left floating during the detection phase.

- Connection to the peripheral to be performed through:
 - An RS232 serial interface (example, ST3232 RS232 transceiver) has to be directly connected to the USART1_RX (PA10) and USART1_TX (PA9) pins when USART1 is used, or to the USART2_RX (PD6) and USART2_TX (PD5) pins when USART2 is used
 - A CAN interface (CAN transceiver) has to be directly connected to the CAN2_RX (PB5) and CAN2_TX (PB13) pins.
 - A certified USB cable has to be connected to the microcontroller (optionally an ESD protection circuitry can be used).

The USART1_CK, USART1_CTS and USART1_RTS pins are not used, therefore the application can use these pins for other peripherals or GPIOs. The same note is applicable for USART3.

The user can control the BOOT0 and Reset pins from a PC serial applet using the RS232 serial interface which controls BOOT0 through the CTS line and Reset through the DCD line. The user must use a full null modem cable. The necessary hardware to implement for this control exists in the STM322xG-EVAL board. For more details about this, refer to the STM322xG-EVAL board user manual, available from the STMicroelectronics website: <http://www.st.com>.

9.2.3 Bootloader selection

The STM32F2xx embedded bootloader V3.x supports three peripheral interfaces: USART1, USART3 (on PB10/PB11 and PC10/PC11), CAN2 and DFU (USB FS Device). Any one of these peripheral interfaces can be used to communicate with the bootloader and download the application code to the internal Flash.

The embedded bootloader firmware is able to auto-detect the peripheral interface to be used. In an infinite loop, it detects any communication on the supported bootloader interfaces.

Note: ***The RX pins of the peripherals not used in this bootloader must be kept at a known (low or high) level and should not be left floating during the detection phase as described below. Refer to [Section 9.2.2: Bootloader hardware requirements](#) for more information.***

To use the USART bootloader on USART1 or USART3, connect the serial cable to the desired interface. Once the bootloader detects the data byte 0x7F on this interface, the bootloader firmware executes the auto-baud rate sequence and then enters a loop, waiting for any USART bootloader command.

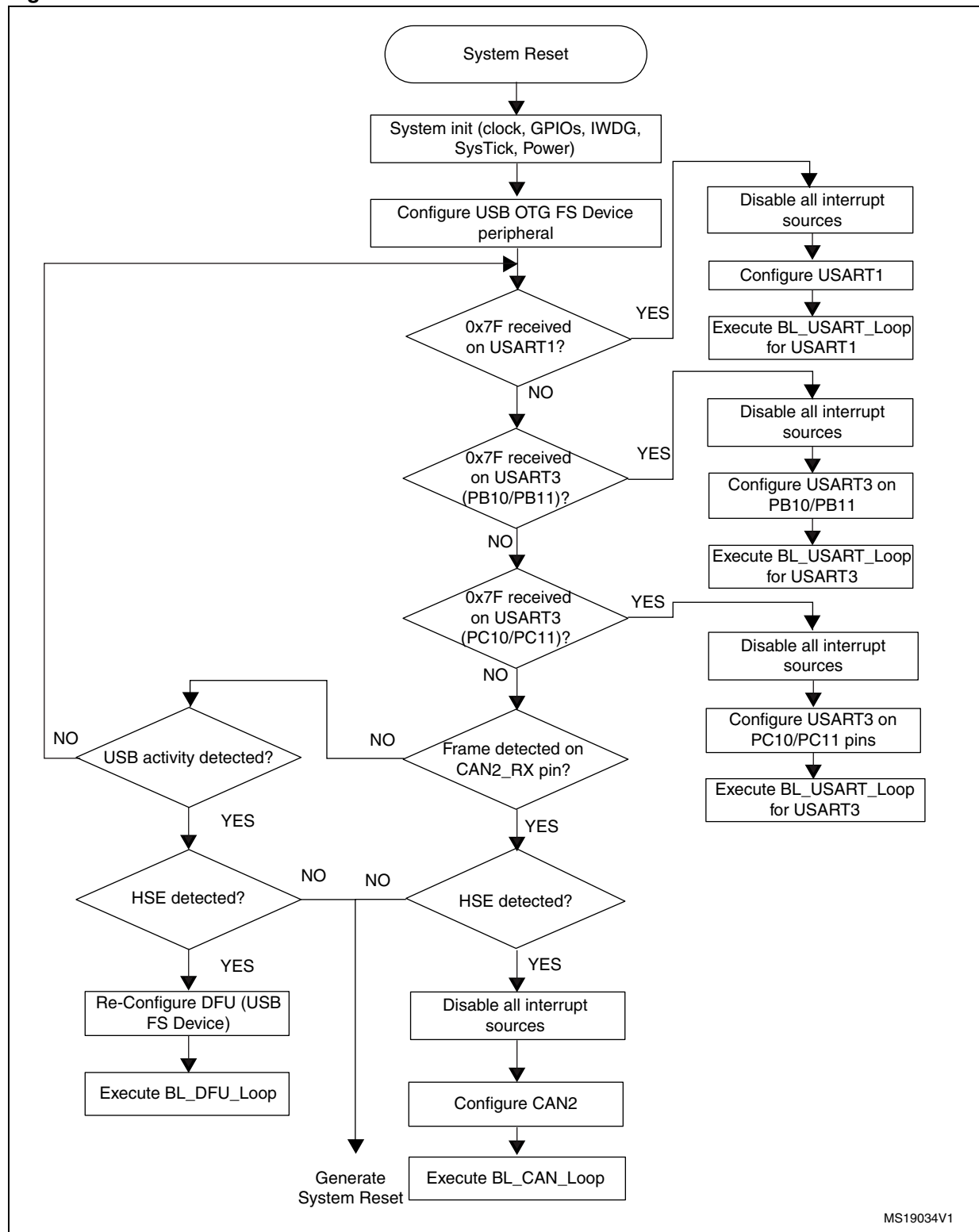
To use the CAN2 interface, connect the CAN cable to CAN2. Once the bootloader detects a frame on the CAN2_RX pin (PB5), the bootloader firmware enters a CAN loop and starts to determine the external clock frequency value. The supported HSE frequencies are multiple of 1 MHz ranging from 4 to 26 MHz. Any other values leads to an unexpected behavior, CAN bootloader firmware enters an infinite loop and waits until it receives a message. If the external clock is not present, a system reset is generated.

If a USB cable is plugged into the microcontroller's USB interface at any time during the bootloader firmware selection sequence, the bootloader enters the DFU bootloader loop waiting for any DFU bootloader command.

To use the USART or the CAN bootloader, it is mandatory that no USB Host is connected to the USB peripheral during the selection phase. Once the USART or CAN bootloader is selected, the user can plug a USB cable without impacting the selected bootloader execution except commands which generate a system reset.

Once one interface is selected for the bootloader, all other interfaces are disabled. The figure below shows the bootloader selection mechanism. More details are provided in the sections corresponding to each peripheral bootloader.

Figure 7. Bootloader V3.x selection for STM32F2xx



9.2.4 Important considerations

STM32F2xx bootloader has some specific features that should be taken into consideration:

- In addition to standard memories (internal Flash, internal SRAM, option bytes and System memory), STM32F2xx device bootloader firmware supports OTP memory (512 bytes from 0x1FFF 7800 to 0x1FFF 7A00, refer to PM0059 programming manual for more information).
- **OTP memory** can be read and written but cannot be erased using Erase command. When writing in an OTP memory location, make sure that the relative protection bit (in the last 16 bytes of the OTP memory) is not reset.

- **Option bytes**

Address is 0x1FFFC000. They allow three levels of protection:

- Level 0
- Level 1
- Level 2

Refer to PM0059 programming manual for more details about protection levels.

- **Read protect** command corresponds to Level 1 protection.
- **Read unprotect** command corresponds to Level 0 protection.
- **Mass erase** command on STM32F2xx takes longer than on other STM32 devices due to their memory density. Make sure that the timeout used by your host interface to wait for an acknowledge event after sending a Mass erase command is sufficient.
- **Voltage Range configuration**

The Voltage Range can be updated on the fly by the bootloader software. The Voltage Range is set to its default value at each bootloader software startup (after system reset or jump to the bootloader code). The bootloader software allows modifying this parameter through a virtual memory location. This memory location is not physical but can be read and written using usual bootloader read/write operations according to the protocol in use (USART, CAN or DFU). This memory location contains 4 bytes which are described in [Table 20](#). It can be accessed by 1, 2, 3 or 4 bytes. However, reserved bytes should remain at their default values (0xFF), otherwise the request will be NACKed.

Table 20. STM32F2xx Voltage Range configuration using bootloader V3.x

Address	Size	Description
0xFFFF0000	1 byte	This byte controls the current value of Voltage Range: 0x00: Voltage Range [1.62V, 2.1V] 0x01: Voltage Range [2.1V, 2.4V] 0x02: Voltage Range [2.4V, 2.7V] 0x03: Voltage Range [2.7V, 3.6V] 0x04: Voltage Range [2.7V, 3.6V] and Double Word write/erase operation is used. In this case it is mandatory to supply 9 V through VPP pin (refer to PM0059 for more details about Double-Word write procedure). Other: All other values are not supported and will be NACKed.
0xFFFF0001	1 byte	Reserved. 0xFF: Default value. Other: all other values are not supported and will be NACKed.
0xFFFF0002	1 byte	Reserved. 0xFF: Default value. Other: all other values are not supported and will be NACKed.
0xFFFF0003	1 byte	Reserved. 0xFF: Default value. Other: all other values are not supported and will be NACKed.

9.2.5 Bootloader version V3.x

[Table 20](#) lists the V3.x versions of STM32F2xx bootloader.

Table 21. STM32F2xx bootloader V3.x versions

Bootloader version number	Description	Known limitations
V3.2	Initial V3.x bootloader version.	<ul style="list-style-type: none"> – When a Read Memory command or Write Memory command is issued with an unsupported memory address and a correct address checksum (ie. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next 2 bytes (which are the number of bytes to be read/written and its checksum) are considered as a new command and its checksum⁽¹⁾. – Option bytes, OTP and Device Feature descriptors (in DFU interface) are set to “g” instead of “e” (not erasable memory areas).
V3.3	Fix V3.2 limitations. DFU interface robustness enhancement.	None

1. If the “number of data - 1” (N-1) to be read/written is not equal to a valid command code (0x00, 0x01, 0x02, 0x11, 0x21, 0x31, 0x43, 0x44, 0x63, 0x73, 0x82 or 0x92), then the limitation is not perceived from the host since the command is NACKed anyway (as an unsupported new command).

10 STM32F405/415xx, and STM32F407/417xx bootloader

Through all this section **STM32F4xx** will be used as reference to STM32F405xx, STM32F407xx, STM32F415xx and STM32F417xx devices.

10.1 Bootloader configuration

The bootloader embedded in STM32F4xx devices support four serial peripherals: USART1, USART3, CAN2, and DFU (USB FS Device).

[Table 19](#) shows the required hardware resources of STM32F4xx devices used by the bootloader in System memory boot mode.

Table 22. STM32F4xx configuration in System memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock is equal to 24 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USARTx interfaces are selected (once CAN or DFU bootloader is selected, the clock source will be derived from external crystal).
		HSE enabled	The system clock is equal to 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS Device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The Clock Security System (CSS) interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	8 Kbytes starting from address 0x2000 0000 are used by the bootloader firmware
	System memory	-	30688 bytes starting from address 0x1FF0 0000, contain the bootloader firmware
	IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (in case the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62V, 2.1V]. The voltage range can be configured in run time using bootloader commands. Note that in this range internal Flash write operations are allowed only in byte format (Half-Word, Word and Double-Word operations are not allowed).

Table 22. STM32F4xx configuration in System memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1 Bootloader	USART1	Enabled	Once initialized the USART1 configuration is: 8-bits, even parity and 1 Stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode
	USART3_RX (PB11), USART3_RX (PC11), CAN2_RX (PB05), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins must be kept at a high or low level during the detection phase.		
USART3 Bootloader (on PB10/PB11)	USART3	Enabled	Once initialized the USART3 configuration is: 8-bits, even parity and 1 Stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode
	USART3_TX pin	Output	PB10pin: USART3 in transmission mode
	USART1_RX (PA10), USART3_RX (PC11), CAN2_RX (PB05), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins must be kept at a high or low level during the detection phase.		
USART3 Bootloader (on PC10/PC11)	USART3	Enabled	Once initialized the USART3 configuration is: 8-bits, even parity and 1 Stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode
	USART3_TX pin	Output	PC10pin: USART3 in transmission mode
	USART1_RX (PA10), USART3_RX (PB11), CAN2_RX (PB05), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins must be kept at a high or low level during the detection phase.		
USART1 and USART3 Bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because STM32F4xx CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB05 pin: CAN2 in reception mode
	CAN2_TX pin	Output	PB13pin: CAN2 in transmission mode
	USART1_RX (PA10), USART3_RX (PB11), USART3_RX (PC11), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins must be kept at a high or low level during the detection phase.		
DFU bootloader	USB_OTG_FS	Enabled	USB OTG FS configured in Forced Device mode. USB_OTG_FS interrupt vector is enabled and used for USB DFU communications.
	USB_OTG_FS_DM pin	Input	PA11 pin: USB OTG FS DM line
	USB_OTG_FS_DP pin	Output	PA12pin: USB OTG FS DP line
	USART1_RX (PA10), USART3_RX (PB11), USART3_RX (PC11) and CAN2_RX (PB05) pins must be kept at a high or low level during the detection phase.		
CAN2 and DFU bootloaders	TIM11	Enabled	This timer is used to determine the value of the external clock frequency. Once the external clock frequency is determined, the RCC system is configured to operate at 60 MHz system clock (using PLL).

Note: *For DFU interface, the external clock source (HSE) is required for USB operations. The detection of the HSE value is done by the Bootloader firmware and is based on the internal oscillator clock (HSI). Thus, when due to temperature or other conditions, the internal oscillator precision is altered above the tolerance band (1% around theoretical value), the Bootloader might calculate a wrong HSE frequency value. In this case, the Bootloader DFU interface might dysfunction or might not work at all.*

The system clock is derived from the embedded internal high-speed RC for USARTx bootloaders. No external quartz is required in this case for the bootloader code. This internal clock is also used for CAN and DFU (USB FS Device) but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

The CAN and DFU bootloaders implement an external clock detection mechanism allowing to determine the value of the external clock using the internal high-speed RC and TIM11 timer. The accuracy of this mechanism allows to detect only frequencies multiple of 1 MHz and ranging from 4 to 26 MHz. Any other value is not supported and will result in unexpected behavior of the bootloader.

After downloading the application binary, if you choose to execute the Go command, the peripheral registers used by the bootloader (shown in the above table) are not initialized to their default reset values before jumping to the user application. They should be reconfigured in the user application if they are used. So, if the IWDG is being used in the application, the IWDG prescaler value has to be adapted to meet the requirements of the application (since the prescaler was set to its maximum value by the bootloader).

10.2 Bootloader hardware requirements

The hardware required to put the STM32F4xx into System memory boot mode consists of any circuitry, switch or jumper, capable of holding the BOOT0 pin high and the BOOT1 pin low during reset.

To connect to the STM32F4xx during System memory boot mode, the following conditions have to be verified:

- The RX pins of the peripheral unused in this bootloader have to be kept at a known (low or high) level, and should not be left floating during the detection phase as described below:
 - If USART1 is used to connect to the bootloader: the USART3_RX (PC11 and PB11), CAN2_RX (PB05), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) pins have to be kept at a high or low level and must not be left floating during the detection phase.
 - If USART3 (on PB10/PB11) is used to connect to the bootloader: the USART1_RX (PA10), USART3_RX (PC11), CAN2_RX (PB05), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) have to be kept at a high or low level and must not be left floating during the detection phase.
 - If USART3 (on PC10/PC11) is used to connect to the bootloader: the USART1_RX (PA10), USART3_RX pin (PB11), CAN2_RX (PB05), OTG_FS_DM (PA11) and OTG_FS_DP (PA12) have to be kept at a high or low level and must not be left floating during the detection phase.
 - If CAN2 is used to connect to the bootloader: the USART1_RX (PA10), USART3_RX (PC11 and PB11), OTG_FS_DM (PA11) and OTG_FS_DP (PA12)

pins have to be kept at a high or low level and must not be left floating during the detection phase.

- If DFU (USB FS Device) is used to connect to the bootloader: the USART1_RX (PA10), USART3_RX (PC11 and PB11) and CAN2_RX (PB05) pins have to be kept at a high or low level and must not be left floating during the detection phase.
- Connection to the peripheral to be performed through:
 - An RS232 serial interface (example, ST3232 RS232 transceiver) has to be directly connected to the USART1_RX (PA10) and USART1_TX (PA9) pins when USART1 is used, or to the USART2_RX (PD6) and USART2_TX (PD5) pins when USART2 is used
 - A CAN interface (CAN transceiver) has to be directly connected to the CAN2_RX (PB5) and CAN2_TX (PB13) pins.
 - A certified USB cable has to be connected to the microcontroller (optionally an ESD protection circuitry can be used).

The USART1_CK, USART1_CTS and USART1_RTS pins are not used, therefore the application can use these pins for other peripherals or GPIOs. The same note is applicable for USART3.

The user can control the BOOT0 and Reset pins from a PC serial applet using the RS232 serial interface which controls BOOT0 through the CTS line and Reset through the DCD line. The user must use a full null modem cable. The necessary hardware to implement for this control exists in the STM324xG-EVAL board. For more details about this, refer to the STM324xG-EVAL board user manual, available from the STMicroelectronics website: <http://www.st.com>.

10.3 Bootloader selection

The STM32F4xx embedded bootloader supports three peripheral interfaces: USART1, USART3 (on PB10/PB11 and PC10/PC11), CAN2 and DFU (USB FS Device). Any one of these peripheral interfaces can be used to communicate with the bootloader and download the application code to the internal Flash.

The embedded bootloader firmware is able to auto-detect the peripheral interface to be used. In an infinite loop, it detects any communication on the supported bootloader interfaces.

Note: *The RX pins of the peripherals not used in this bootloader must be kept at a known (low or high) level and should not be left floating during the detection phase as described below. Refer to [Section 10.2: Bootloader hardware requirements](#) for more information.*

To use the USART bootloader on USART1 or USART3, connect the serial cable to the desired interface. Once the bootloader detects the data byte 0x7F on this interface, the bootloader firmware executes the auto-baud rate sequence and then enters a loop, waiting for any USART bootloader command.

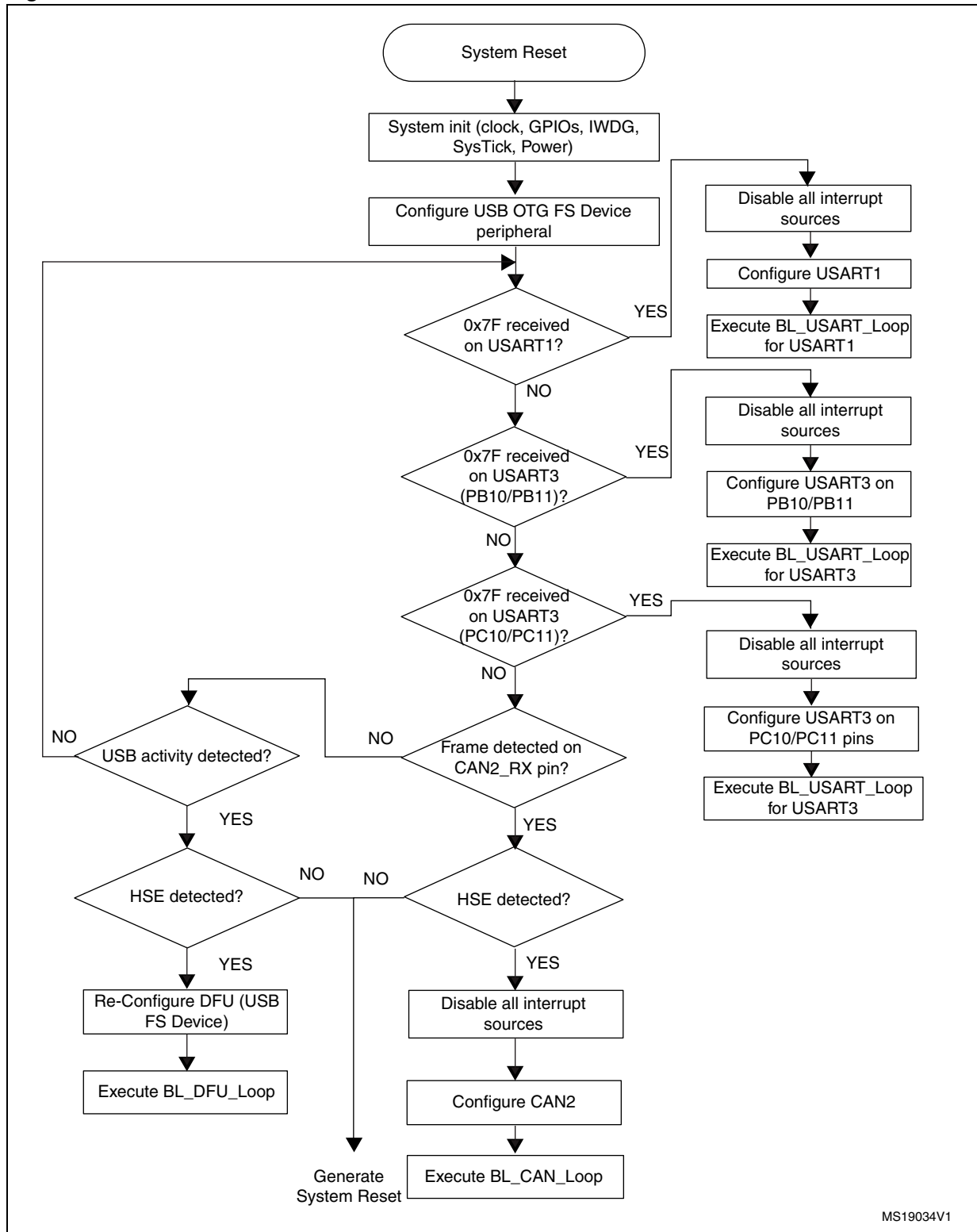
To use the CAN2 interface, connect the CAN cable to CAN2. Once the bootloader detects a frame on the CAN2_RX pin (PB5), the bootloader firmware enters a CAN loop and starts to determine the external clock frequency value. The supported HSE frequencies are multiple of 1 MHz ranging from 4 to 26 MHz. Any other values leads to an unexpected behavior, CAN bootloader firmware enters an infinite loop and waits until it receives a message. If the external clock is not present, a system reset is generated.

If a USB cable is plugged into the microcontroller's USB interface at any time during the bootloader firmware selection sequence, the bootloader enters the DFU bootloader loop waiting for any DFU bootloader command.

To use the USART or the CAN bootloader, it is mandatory that no USB Host is connected to the USB peripheral during the selection phase. Once the USART or CAN bootloader is selected, the user can plug a USB cable without impacting the selected bootloader execution except commands which generate a system reset.

Once one interface is selected for the bootloader, all other interfaces are disabled. The figure below shows the bootloader selection mechanism. More details are provided in the sections corresponding to each peripheral bootloader.

Figure 8. Bootloader selection for STM32F4xx



10.4 Important considerations

STM32F4xx bootloader has some specific features that should be taken into consideration:

- In addition to standard memories (internal Flash, internal SRAM, option bytes and System memory), STM32F4xx device bootloader firmware supports OTP memory (512 bytes from 0x1FFF 7800 to 0x1FFF 7A00, refer to PM0081 programming manual for more information).
- **OTP memory** can be read and written but cannot be erased using Erase command. When writing in an OTP memory location, make sure that the relative protection bit (in the last 16 bytes of the OTP memory) is not reset.

- **Option bytes**

Address is 0x1FFFC000. They allow three levels of protection:

- Level 0
- Level 1
- Level 2

Refer to PM0081 programming manual for more details about protection levels.

- **Read protect** command corresponds to Level 1 protection.
- **Read unprotect** command corresponds to Level 0 protection.
- **Mass erase** command on STM32F4xx takes longer than on other STM32 devices due to their memory density. Make sure that the timeout used by your host interface to wait for an acknowledge event after sending a Mass erase command is sufficient.
- **Voltage Range configuration**

The Voltage Range can be updated on the fly by the bootloader software. The Voltage Range is set to its default value at each bootloader software startup (after system reset or jump to the bootloader code). The bootloader software allows modifying this parameter through a virtual memory location. This memory location is not physical but can be read and written using usual bootloader read/write operations according to the protocol in use (USART, CAN or DFU). This memory location contains 4 bytes which are described in [Table 20](#). It can be accessed by 1, 2, 3 or 4 bytes. However, reserved bytes should remain at their default values (0xFF), otherwise the request will be NACKed.

Table 23. STM32F4xx Voltage Range configuration using bootloader

Address	Size	Description
0xFFFF0000	1 byte	This byte controls the current value of Voltage Range: 0x00: Voltage Range [1.62V, 2.1V] 0x01: Voltage Range [2.1V, 2.4V] 0x02: Voltage Range [2.4V, 2.7V] 0x03: Voltage Range [2.7V, 3.6V] 0x04: Voltage Range [2.7V, 3.6V] and Double Word write/erase operation is used. In this case it is mandatory to supply 9 V through VPP pin (refer to PM0081 for more details about Double-Word write procedure). Other: All other values are not supported and will be NACKed.
0xFFFF0001	1 byte	Reserved. 0xFF: Default value. Other: all other values are not supported and will be NACKed.
0xFFFF0002	1 byte	Reserved. 0xFF: Default value. Other: all other values are not supported and will be NACKed.
0xFFFF0003	1 byte	Reserved. 0xFF: Default value. Other: all other values are not supported and will be NACKed.

10.5 Bootloader version

Table 20 shows the STM32F4xx bootloader version.

Table 24. STM32F4xx bootloader version

Bootloader version number	Description	Known limitations
V3.0	Initial bootloader version.	<ul style="list-style-type: none"> – When a Read Memory command or Write Memory command is issued with an unsupported memory address and a correct address checksum (ie. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next 2 bytes (which are the number of bytes to be read/written and its checksum) are considered as a new command and its checksum⁽¹⁾. – Option bytes, OTP and Device Feature descriptors (in DFU interface) are set to “g” instead of “e” (not erasable memory areas).
V3.1	Fix V3.0 limitations. DFU interface robustness enhancement.	None

1. If the “number of data - 1” (N-1) to be read/written is not equal to a valid command code (0x00, 0x01, 0x02, 0x11, 0x21, 0x31, 0x43, 0x44, 0x63, 0x73, 0x82 or 0x92), then the limitation is not perceived from the host since the command is NACKed anyway (as an unsupported new command).

11 STM32F051x6 and STM32F051x8 device bootloader

Through all this section STM32F051xx will be used as reference to STM32F051x6 and STM32F051x8 devices.

11.1 Bootloader configuration

The bootloader embedded in STM32F051xx devices supports two serial interfaces: USART1 and USART2 peripherals.

The following table shows the required hardware resources of STM32F051xx devices used by the bootloader in System memory boot mode.

Table 25. STM32F51xx configuration in System memory boot mode

Feature/Peripheral	State	Comment
Clock Source	HSI Enabled	The System clock is equal to 24 MHz (using PLL clocked by HSI). 1 Flash Wait State.
USART1_RX pin	Input	PA10 pin: USART1 in reception mode.
USART1_TX pin	Output	PA9 pin: USART1 in transmission mode.
USART2_RX pin	Input	PA14 pin: USART2 in reception mode.
USART2_TX pin	Output	PA15 pin: USART2 in transmission mode.
SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.
USART1	Enabled	Once initialized, the USART1 configuration is 8-bits, even parity and 1 Stop bit.
USART2	Enabled	Once initialized the USART2 configuration is 8-bits, even parity and 1 Stop bit.
RAM	-	2 Kbytes starting from address 0x2000 0000 are used by the bootloader firmware.
System memory	-	3 Kbytes starting from address 0x1FFF EC00, contain the bootloader firmware.
IWDG	-	The independent watchdog (IWDG) prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset in case the hardware IWDG option was previously enabled by the user.

Note: *After the STM32F051x6 and STM32F051x8 devices have booted in Bootloader mode, the serial wire debug (SWD) communication is no more possible until the system is reset, because SWD uses PA14 pin (SWCLK) which is already used by the Bootloader (USART2_RX).*

11.2 Bootloader hardware requirements

The hardware required to put the STM32F051xx devices into System memory boot mode consists of any circuitry, switch or jumper, capable of holding the BOOT0 pin high while

BOOT1 bit in the option bytes (starting at address 0x1FFFF 8002) is set to value 1. The setting of this bit can be done through STLINK utility or an equivalent tool.

To connect to the STM32F051xx devices during System memory boot mode, the following conditions have to be verified:

- The peripheral RX pins not used in this bootloader have to be kept at a known (low or high) level, and should not be left floating during the detection phase as described below:
 - If USART1 is used to connect to the bootloader, the USART2_RX (PA15) pin has to be kept at a high or low level and must not be left floating during the detection phase.
 - If USART2 is used to connect to the bootloader, the USART1_RX (PA10) pin has to be kept at a high or low level and must not be left floating during the detection phase.
- The peripheral to be used has to be connected through an RS232 serial interface (example, ST3232 RS232 transceiver) which must be:
 - directly connected to the USART1_RX (PA10) and USART1_TX (PA9) pins when USART1 is used
 - directly connected to the USART2_RX (PA15) and USART2_TX (PA14) pins when USART2 is used.
- The USART1_CK, USART1_CTS and USART1_RTS pins are not used. As a result, the application can use these pins for other peripherals or GPIOs. The same note is applicable for USART2.

The user can control the BOOT0 and Reset pins from a PC serial applet using the RS232 serial interface which controls BOOT0 through the CTS line and Reset through the DCD line. The user must use a full null modem cable. The necessary hardware to implement for this control exists in the STM320518-EVAL board. For more details about this, refer to the “STM320518-EVAL board user manual” (UM1537), available from the STMicroelectronics website: <http://www.st.com>.

11.3 Bootloader selection

The STM32F051xx devices embedded bootloader supports two peripheral interfaces: USART1 and USART2. Any one of these peripheral interfaces can be used to communicate with the bootloader and download the application code to the internal Flash memory.

The embedded bootloader firmware is able to auto-detect the peripheral interface to be used. In an infinite loop, it detects any communication on the supported bootloader interfaces.

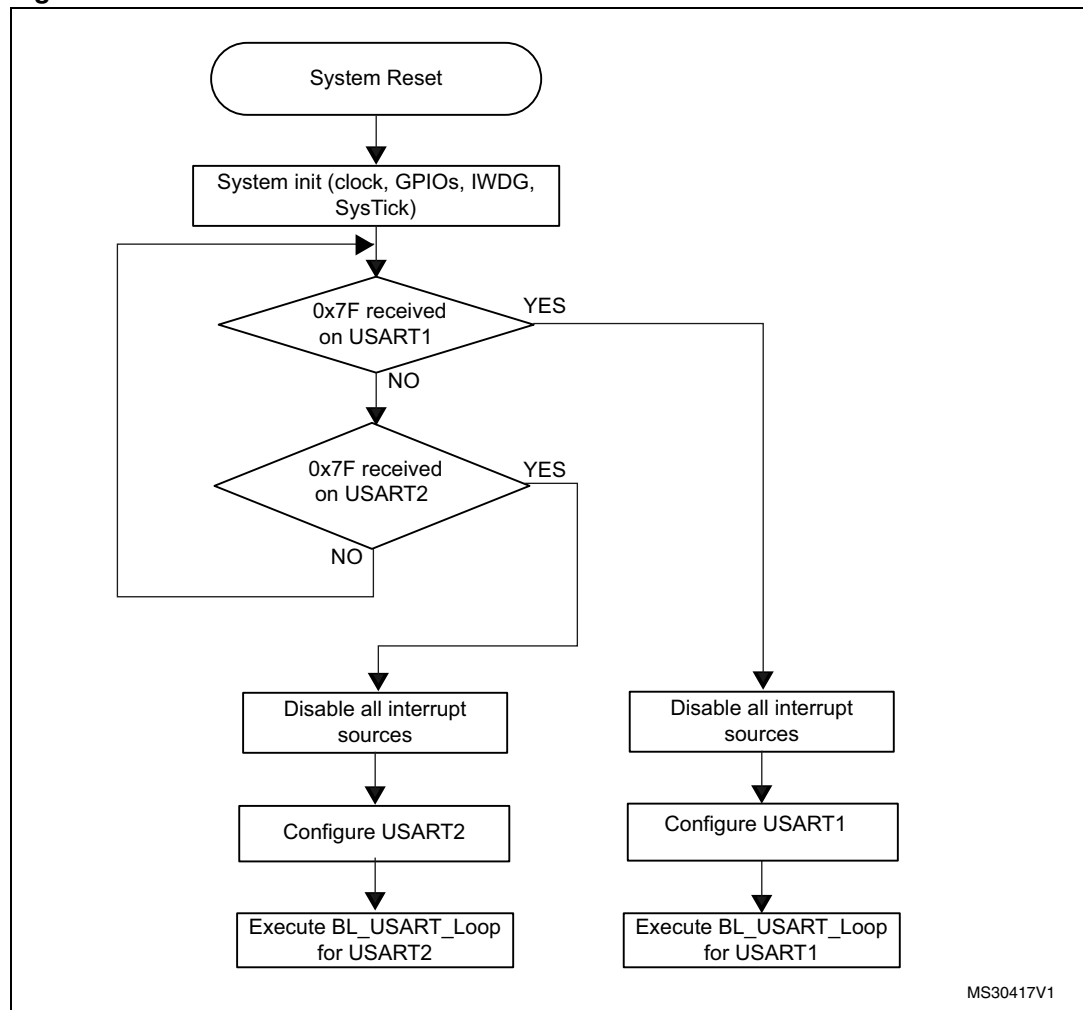
Note: *The RX pins of the peripherals which are not used by this bootloader must be kept at a known (low or high) level and should not be left floating during the detection phase as described below. Refer to [Section 11.2: Bootloader hardware requirements](#) for more information.*

To use the USART bootloader on USART1 or USART2, connect the serial cable to the desired interface. Once the bootloader detects the data byte 0x7F on this interface, the bootloader firmware executes the autobaudrate sequence and then enters a loop, waiting for any USART bootloader command.

Once one interface is selected for the bootloader, and the other interface is disabled.

The figure below shows the bootloader detection mechanism. More details are provided in the sections corresponding to each peripheral bootloader.

Figure 9. Bootloader selection for STM32F051xx



11.4 Important considerations

The bootloader of the STM32F051xx devices has some specific features that should be taken into consideration, as described below:

- Option byte

Address is 0x1FF8 0000. They allow three levels of protection:

 - Level 0
 - Level 1
 - Level 2

Refer to RM0091 reference manual for more details about protection levels.
- Read protect command corresponds to the Level 1 protection.
- Read unprotect command corresponds to the Level 0 protection.
- Jump to user application

If an application that uses interrupts has to be downloaded to Flash memory address 0x0800 0000 by the Bootloader firmware, then that application must at startup and before any interrupt is enabled, map the Flash memory by software to the address 0x0000 0000. This can be done by programming the MEM_MODE bits of the SYSCFG_CFGR1 register (refer to RM0091 reference manual for more details about software memory mapping).

If the application is loaded into Flash memory at an address different from 0x08000000, then the vector table has to be mapped to SRAM and the SRAM should in this case be mapped by software to address 0x0000 0000.

11.5 Bootloader version

The following table lists the STM32F051xx bootloader versions:

Table 26. STM32F051xx bootloader versions

Bootloader version number	Description	Known limitations
V2.1	Initial bootloader version	When the user application configures a value of HSI TRIM bits (in RCC_CR register) and then jumps to the bootloader, the HSITRIM value is reset to its default value (0) at Bootloader startup.

12 Device-dependent bootloader parameters

The bootloader protocol's command set and sequences for each serial peripheral (USART, CAN and USB) are the same for all STM32 devices. Some parameters, however, are device-dependent. For a few commands, the value of some parameters may depend on the device used. These parameters are listed below:

- PID (product ID), which changes with the device
- Valid memory addresses (RAM, Flash memory, System memory, option byte area) accepted by the bootloader when the Read Memory, Go and Write Memory commands are accepted.
- Size of the Flash memory sector used when executing the Write Protect command.

The table below shows the values of these parameters for each STM32 device bootloader in production.

Table 27. Bootloader device-dependant parameters

Device	Product (device) ID	RAM memory	Flash memory	Flash sector size	Option byte area	System memory
Low-density	0x412	0x20000200 up to 0x20002800	0x08000000 up to 0x08008000	4 Kbytes (4 pages of 1 Kbyte each)	0x1FFFF800 - 0x1FFFF80F	0x1FFF0000 - 0x1FFF8000
Medium-density	0x410	0x20000200 up to 0x20005000	0x08000000 up to 0x08020000	4 Kbytes (4 pages of 1 Kbyte each)	0x1FFFF800 - 0x1FFFF80F	0x1FFF0000 - 0x1FFF8000
High-density	0x414	0x20000200 up to 0x20010000	0x08000000 up to 0x08080000	4 Kbytes (2 pages of 2 Kbytes each)	0x1FFFF800 - 0x1FFFF80F	0x1FFF0000 - 0x1FFF8000
Connectivity line	0x418	0x20001000 up to 0x20010000	0x08000000 up to 0x08040000	4 Kbytes (2 pages of 2 Kbytes each)	0x1FFFF800 - 0x1FFFF80F	0x1FFFB000 - 0x1FFFF800
Medium-density value line	0x420	0x20000200 up to 0x20002000	0x08000000 up to 0x08020000	4 Kbytes (4 pages of 1 Kbyte each)	0x1FFFF800 - 0x1FFFF80F	0x1FFF0000 - 0x1FFF8000
High-density value line	0x428	0x20000200 up to 0x20008000	0x08000000 up to 0x08080000	4 Kbytes (2 pages of 2 Kbytes each)	0x1FFFF800 - 0x1FFFF80F	0x1FFF0000 - 0x1FFF8000
XL-density	0x430	0x20000800 up to 0x20018000	0x08000000 up to 0x08100000	4 Kbytes (2 pages of 2 Kbytes each)	0x1FFFF800 - 0x1FFFF80F	0x1FFFE000 - 0x1FFF8000
Medium-density ultralow power line	0x436	0x20001000 up to 0x2000C000	0x08000000 up to 0x08060000	4 Kbytes (16 pages of 256 Bytes each)	0x1FF80000 - 0x1FF8000F	0x1FF00000 - 0x1FF01000
High-density ultralow power line	0x416	0x20000800 up to 0x20004000	0x08000000 up to 0x08020000	4 Kbytes (16 pages of 256 Bytes each)	0x1FF80000 - 0x1FF80020	0x1FF00000 - 0x1FF02000
STM32F2xx devices	0x411	0x20002000 up to 0x20020000	0x08000000 up to 0x08100000	12 sectors (4x16Kbytes, 1x64Kbytes, 7x128Kbytes)	0x1FFFC000 - 0x1FFFC00F	0x1FFF0000 - 0x1FFF77FF

Table 27. Bootloader device-dependant parameters (continued)

Device	Product (device) ID	RAM memory	Flash memory	Flash sector size	Option byte area	System memory
STM32F4xx devices	0x413	0x20002000 up to 0x20020000	0x08000000 up to 0x08100000	12 sectors (4x16Kbytes, 1x64Kbytes, 7x128Kbytes)	0x1FFFC000-0x1FFFC00F	0x1FFF0000 - 0x1FFF77FF
STM32F051x6 and STM32F051x8 devices	0x440	0x20000800 up to 0x20002000	0x08000000 up to 0x08010000	4 Kbytes (4 pages of 1 Kbytes each)	0x1FFFF800 - 0x1FFFF80B	0x1FFFE000 - 0x1FFFF800

13 Bootloader timing characteristics

This section presents the main startup timings of the bootloader firmware depending on products. They can be used to set up the connection timeout, that is how long the host waits before synchronization with the bootloader is established.

Three types of timings will be described herein:

- Hardware-dependent timings relative to product and directly extracted from the product datasheet.
- Communication-dependent timings relative to the baudrate and data traffic on the bus. These timings depend only on the communication interface configuration and on the host behavior.
- Bootloader software-dependent timings relative to bootloader software operations.

All the timings described in this section are expressed in milliseconds (ms) except when otherwise specified.

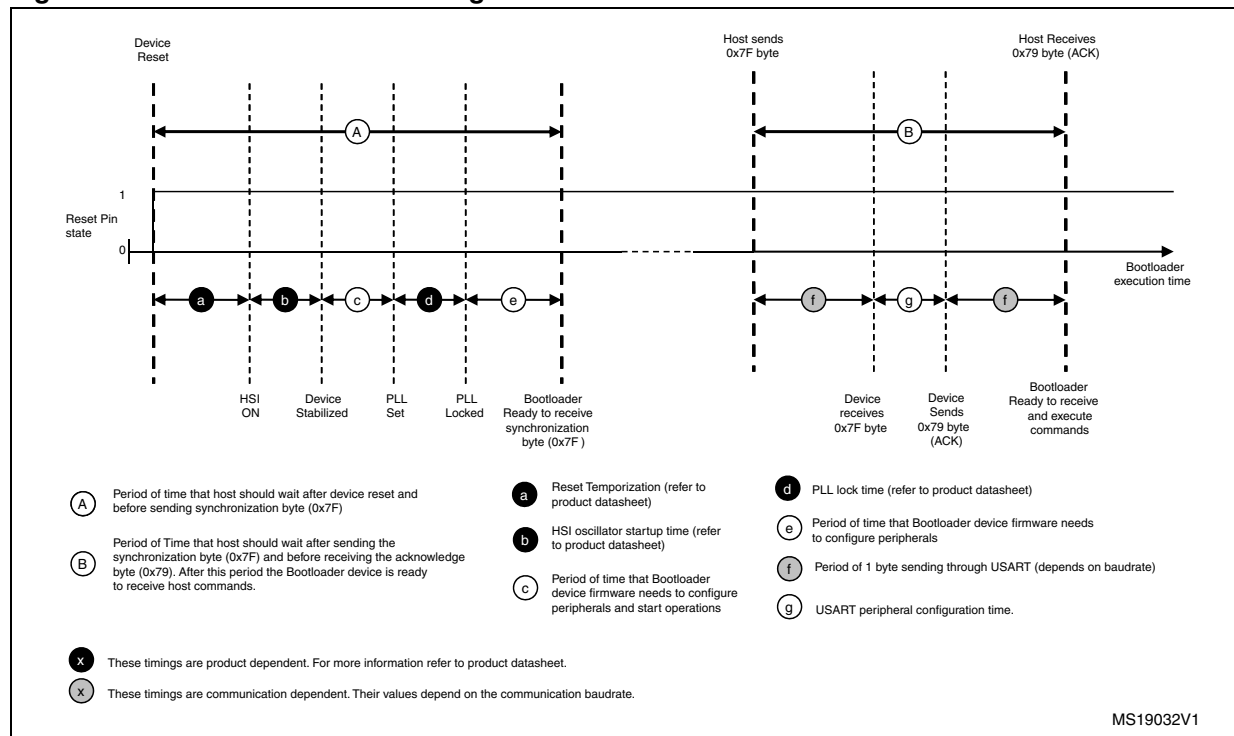
13.1 USART bootloader timing characteristics

Two main timings need to be considered for host operations when using the USART bootloader:

- Timing A
After bootloader reset, this timing corresponds to the time during which the host waits before sending the synchronization data (0x7F) to properly configure the bootloader baudrate detection. This timing will be referred to as **A** throughout this section.
- Timing B
After sending the synchronization data (0x7F), this timing corresponds to the time during which the host waits before receiving the first acknowledge response (meaning that the bootloader is ready to receive and execute host commands). This timing will be referred to as **B** throughout this section.

A and **B** timings are composed of different sub-timings as described in [Figure 10](#).

Figure 10. USART bootloader timing waveforms



The timing values for each product are listed in [Table 28](#), [Table 29](#), [Table 30](#), [Table 31](#), [Table 32](#), [Table 33](#), [Table 34](#), [Table 35](#), and [Table 36](#).

Table 28. USART bootloader timings for low/medium/high-density and value line devices

Time	Description	Min	Max	Unit
a	Reset temporization	1	4.5	ms
b	HSI oscillator startup time	0.001	0.002	ms
c	Bootloader firmware operations	0.004	-	ms
d	PLL Lock time	0.2	-	ms
e	Bootloader firmware operations	0.002	-	ms
f	One USART byte sending period	0.078125	7.5	ms
g	Bootloader firmware operations	0.002	-	ms
A	Time = a + b + c + d + e	1.207	4.708	ms
B	Time = (2 x f) + g	0.15825	15.002	ms

Table 29. USART bootloader timings for XL-density line devices

Time	Description	Min	Max	Unit
a	Reset temporization	1	4.5	ms
b	HSI oscillator startup time	0.001	0.002	ms
c	Bootloader firmware operations	0.02	-	ms
d	PLL Lock time	0.2	-	ms
e	Bootloader firmware operations	0.006	-	ms
f	One USART byte sending period	0.078125	7.5	ms
g	Bootloader firmware operations	0.006	-	ms
A	Time = a + b + c + d + e	1.227	4.728	ms
B	Time = (2 x f) + g	0.16225	15.006	ms

Table 30. USART bootloader timings for connectivity line devices (PA9 pin low)

Time	Description	Min	Max	Unit
a	Reset temporization	1	4.5	ms
b	HSI oscillator startup time	0.001	0.002	ms
c	Bootloader firmware operations	0.025	-	ms
d	PLL Lock time	0.35	-	ms
e	Bootloader firmware operations	0.02	-	ms
f	One USART byte sending period	0.078125	7.5	ms
g	Bootloader firmware operations	0.007	-	ms
A	Time = a + b + c + d + e	1.396	4.897	ms
B	Time = (2 x f) + g	0.16325	15.007	ms

For connectivity line devices, PA9 pin (USB_VBUS) is used to detect the USB host connection. The initialization of USB peripheral is performed only if PA9 is high at detection phase which means that a host is connected to the port and delivering 5 V on the USB bus. When PA9 level is high at detection phase, more time is required to initialize and shutdown the USB peripheral.

To minimize bootloader detection time for connectivity line devices when PA9 pin is not used, keep PA9 state low during detection phase from the moment the device is reset till a device ACK is sent.

Table 31. USART bootloader timings for connectivity line devices (PA9 high)

Time	Description	Min	Max	Unit
a	Reset temporization	1	4.5	ms
b	HSI oscillator startup time	0.001	0.002	ms
c	Bootloader firmware operations	0.025	-	ms
d	PLL Lock time	0.35	-	ms
e	Bootloader firmware operations	523	-	ms
f	One USART byte sending period	0.078125	7.5	ms
g	Bootloader firmware operations	105	-	ms
A	Time = a + b + c + d + e	524.376	527.877	ms
B	Time = (2 x f) + g	105.1563	120	ms

Table 32. USART bootloader timings for STM32L15xx medium-density ultralow power devices

Time	Description	Min	Max	Unit
a	Reset temporization	0.4	1.6	ms
b	MSI oscillator stabilization time	-	0.04	ms
c	Bootloader firmware operations	0.064	-	ms
d	HSI oscillator startup time	0.0037	0.006	ms
e	Bootloader firmware operations	0.034	-	ms
f	One USART byte sending period	0.078125	7.5	ms
g	Bootloader firmware operations	0.008	-	ms
A	Time = a + b + c + d + e	0.5417	1.744	ms
B	Time = (2 x f) + g	0.16425	15.008	ms

Table 33. USART bootloader timings for STM32L15xx high-density ultralow power devices

Time	Description	Min	Max	Unit
a	Reset Temporization	0.4	1.6	ms
b	MSI oscillator stabilization time		0.07	ms
c	Bootloader firmware operations	0.058		ms
d	HSI oscillator startup time		0.006	ms
e	Bootloader firmware operations	0.174		ms

Table 33. USART bootloader timings for STM32L15xx high-density ultralow power devices

f	One USART byte sending period	0.078125	7.5	ms
g	Bootloader firmware operations	0.0078		ms
A	Time = a + b + c + d + e	0.708	1.908	ms
B	Time = (2 x f) + g	0.16405	15.0078	ms

Table 34. USART bootloader timings for STM32F205/215xx and STM32F207/217xx devices

Time	Description	Min	Max	Unit
a	Reset temporization	0.5	3.0	ms
b	HSI oscillator startup time	0.0022	0.004	ms
c	Bootloader firmware operations	0.01	-	ms
d	PLL Lock time	0.075	0.2	ms
e	Bootloader firmware operations	84	-	ms
f	One USART byte sending period	0.078125	7.5	ms
g	Bootloader firmware operations	0.009	-	ms
A	Time = a + b + c + d + e	84.5872	87.214	ms
B	Time = (2 x f) + g	0.16525	15.009	ms

Table 35. USART bootloader timings for STM32F405/415xx and STM32F407/417xx devices

Time	Description	Min	Max	Unit
a	Reset temporization	0.5	3.0	ms
b	HSI oscillator startup time	0.0022	0.004	ms
c	Bootloader firmware operations	0.01	-	ms
d	PLL Lock time	0.075	0.2	ms
e	Bootloader firmware operations	84	-	ms
f	One USART byte sending period	0.078125	7.5	ms
g	Bootloader firmware operations	0.009	-	ms
A	Time = a + b + c + d + e	84.5872	87.214	ms
B	Time = (2 x f) + g	0.16525	15.009	ms

Table 36. USART bootloader timings for STM32F051x6 and STM32F051x8 devices

Time	Description	Min	Max	Unit
a	Reset Temporization	1.5	4.5	ms
b	HSI oscillator startup time	0.001	0.002	ms
c + d + e	Bootloader firmware operations	0.111		ms
f	One USART byte sending period	0.078125	7.5	ms
g	Bootloader firmware operations	0.0095		ms
A	Time = a + b + c + d + e	1.612	4.613	ms
B	Time = (2 x f) + g	0.16575	15.0095	ms

13.2 USB bootloader timing characteristics

The main timings that need to be considered for host operations when using the USB bootloader are the following:

- Timing A

After bootloader reset, this timing corresponds to the time during which the host waits before starting the connection sequence with the device. It is similar to the USART connection timeout described in [Section 13.1](#). It will be referred to as **A** throughout this section.

- Timing B

When the connection sequence has started, this timing corresponds to the time required by the device to establish a correct connection with the host (meaning that the bootloader is ready to receive and execute host commands). This timing includes enumerations and DFU components configuration (e.g. internal Flash memory). This timing will be referred to as **B** throughout this section.

For connectivity line devices, if the external HSE crystal frequency is different from 25 MHz (14.7456 MHz or 8 MHz), the device performs several unsuccessful enumerations (with connect – disconnect sequences) before being able to establish a correct connection with the host. This is due to the HSE automatic detection mechanism based on SOF detection.

A and **B** timings are composed of different sub-timings as described in [Figure 11](#). Refer to [Table 28](#), [Table 29](#), [Table 30](#), [Table 31](#), [Table 32](#), [Table 33](#), [Table 34](#), [Table 35](#), and [Table 36](#) for the values of timing A (identical to USART bootloader), and to [Table 37](#), [Table 38](#), [Table 39](#), and [Table 40](#) for the values of timing B.

Note: *For USB interface, only minimum timings are provided since the connection timing depends on environment and host configuration (number of nodes (hubs), host speed, traffic on the USB bus, host loading ...).*

Figure 11. USB bootloader timing waveforms

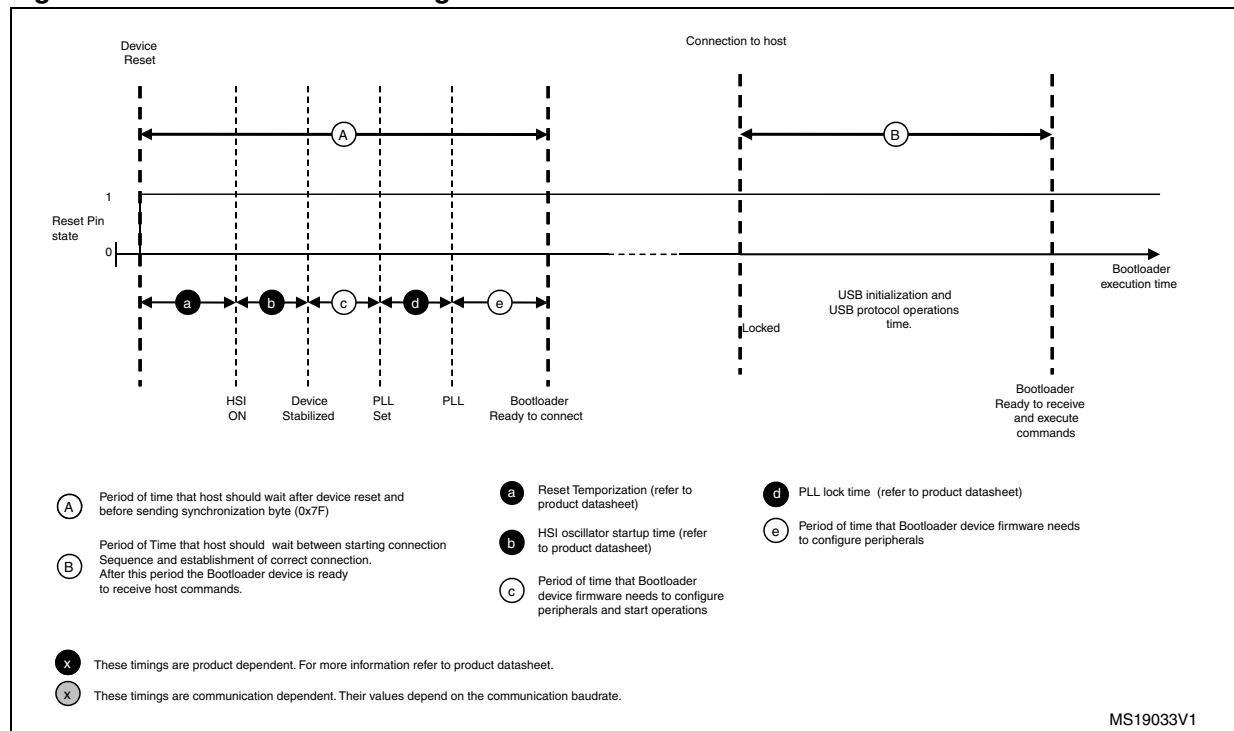


Table 37. USB minimum timings for connectivity line devices

Time	Description	25MHz	14.7456MHz	8MHz	Unit
a	Reset temporization	1	1	1	ms
b	HSI oscillator startup time	0.001	0.001	0.001	ms
c	Bootloader firmware operations	0.025	0.025	0.025	ms
d	PLL Lock time	0.35	0.35	0.35	ms
e	Bootloader firmware operations	523	523	523	ms
A	Time = a + b + c + d + e	524.376	524.376	524.376	ms
B	Connection establishment	460	4500	13700	ms

Table 38. USB minimum timings for STM32L15xx high-density ultralow power devices

Time	Description	Min	Unit
a	Reset Temporization	0.4	ms
b	MSI oscillator stabilization time	0.07	ms
c	Bootloader firmware operations	0.058	ms

Table 38. USB minimum timings for STM32L15xx high-density ultralow power devices (continued)

Time	Description	Min	Unit
d	HSI oscillator startup time	0.0037	ms
e	Bootloader firmware operations	0.174	ms
A	Time = a + b + c + d + e	0.7057	ms
B	Connection establishment	849	ms

Table 39. USB minimum timings for STM32F205/215xx, and STM32F207/217xx devices

Time	Description	Min	Unit
a	Reset temporization	0.5	ms
b	HSI oscillator startup time	0.0022	ms
c	Bootloader firmware operations	0.01	ms
d	PLL Lock time	0.075	ms
e	Bootloader firmware operations	84	ms
A	Time = a + b + c + d + e	84.5872	ms
B	Connection establishment	54	ms

Table 40. USB minimum timings for STM32F405/415xx, and STM32F407/417xx devices

Time	Description	Min	Unit
a	Reset temporization	0.5	ms
b	HSI oscillator startup time	0.0022	ms
c	Bootloader firmware operations	0.01	ms
d	PLL Lock time	0.075	ms
e	Bootloader firmware operations	84	ms
A	Time = a + b + c + d + e	84.5872	ms
B	Connection establishment	54	ms

For the STM32F2xx and STM32F4xx devices bootloader, the timing values are independent from the HSE crystal frequency. The detection of the HSE crystal frequency value is performed through period measurement using TIM11 timer and HSI internal oscillator.

14 Revision history

Table 41. Document revision history

Date	Revision	Changes
22-Oct-2007	1	Initial release.
22-Jan-2008	2	<p>All STM32 in production (rev. B and rev. Z) include the bootloader described in this application note.</p> <p>Modified: Section 3.1: Bootloader activation and Section 1.4: Bootloader code sequence.</p> <p>Added: Section 1.3: Hardware requirements, Section 1.5: Choosing the USART baud rate, Section 1.6: Using the bootloader and Section 3.2: Exiting System memory boot mode.</p> <p>Note 2 linked to Get, Get Version & Read Protection Status and Get ID commands in Table 3: Bootloader commands, Note 3 added.</p> <p>Notion of “permanent” (Permanent Write Unprotect/Readout Protect/Unprotect) removed from document. Small text changes.</p> <p>Bootloader version upgraded to 2.0.</p>
26-May-2008	3	<p>Small text changes. RAM and System memory added to Table 4: STM32F10xxx configuration in System memory boot mode.</p> <p>Section 1.6: Using the bootloader on page 8 removed.</p> <p>Erase modified, Note 3 modified and Note 1 added in Table 3: Bootloader commands on page 9.</p> <p>Byte 3: on page 11 modified.</p> <p>Byte 2: on page 13 modified.</p> <p>Byte 2:, Bytes 3-4: and Byte 5: on page 15 modified, Note 3 modified.</p> <p>Byte 8: on page 18 modified.</p> <p>Notes added to Section 2.5: Go command on page 18.</p> <p>Figure 11: Go command: device side on page 20 modified.</p> <p>Note added in Section 2.6: Write Memory command on page 21.</p> <p>Byte 8: on page 24 modified.</p> <p>Figure 14: Erase Memory command: host side and Figure 15: Erase Memory command: device side modified.</p> <p>Byte 3: on page 26 modified.</p> <p>Table 3: Bootloader commands on page 9.</p> <p>Note modified and note added in Section 2.8: Write Protect command on page 27.</p> <p>Figure 16: Write Protect command: host side, Figure 17: Write Protect command: device side, Figure 19: Write Unprotect command: device side, Figure 21: Readout Protect command: device side and Figure 23: Readout Unprotect command: device side modified.</p>
29-Jan-2009	4	<p>This application note also applies to the STM32F102xx microcontrollers.</p> <p>Bootloader version updated to V2.2 (see Table 4: Bootloader versions).</p>

Table 41. Document revision history (continued)

Date	Revision	Changes
19-Nov-2009	5	<p>IWDG added to Table 4: STM32F10xxx configuration in System memory boot mode. Note added.</p> <p>BL changed bootloader in the entire document.</p> <p>Go command description modified in Table 4: STM32F10xxx configuration in System memory boot mode.</p> <p>Number of bytes awaited by the bootloader corrected in Section 2.4: Read Memory command.</p> <p>Note modified below Figure 10: Go command: host side.</p> <p>Note removed in Section 2.5: Go command and note added.</p> <p>Start RAM address specified and note added in Section 2.6: Write Memory command. All options are erased when a Write Memory command is issued to the Option byte area.</p> <p>Figure 11: Go command: device side modified.</p> <p>Figure 13: Write Memory command: device side modified.</p> <p>Note added and bytes 3 and 4 sent by the host modified in Section 2.7: Erase Memory command.</p> <p>Note added to Section 2.8: Write Protect command.</p>
09-Mar-2010	6	<p>Application note restructured. Value line and connectivity line device bootloader added (Replaces AN2662).</p> <p>Introduction changed. Glossary added.</p>
20-Apr-2010	7	<p>Related documents: added XL-density line datasheets and programming manual.</p> <p>Glossary: added XL-density line devices.</p> <p>Table 3: added information for XL-density line devices.</p> <p>Section 4.1: Bootloader configuration: updated first sentence.</p> <p>Section 5.1: Bootloader configuration: updated first sentence.</p> <p>Added Section 6: STM32F101xx and STM32F103xx XL-density device bootloader.</p> <p>Table 27: added information for XL-density line devices.</p>
08-Oct-2010	8	Added information for high-density value line devices in Table 3 and Table 27 .
14-Oct-2010	9	Removed references to obsolete devices.
26-Nov-2010	10	Added information on ultralow power devices.
13-Apr-2011	11	<p>Added information related to STM32F205/215xx and STM32F207/217xx devices.</p> <p>Added Section 13: Bootloader timing characteristics</p>
06-Jun-2011	12	<p>Updated:</p> <ul style="list-style-type: none"> – Table 12: STM32L15xxx bootloader versions – Table 16: STM32F2xx configuration in System memory boot mode – Table 18: STM32F2xx bootloader V2.x versions – Table 21: STM32F2xx bootloader V3.x versions

Table 41. Document revision history (continued)

Date	Revision	Changes
28-Nov-2011	13	<p>Added information related to STM32F405/415xx and STM32F407/417xx bootloader, and STM32F105xx/107xx bootloader V2.1.</p> <p>Added value line devices in Section 4: STM32F100xx, STM32F101xx, STM32F102xx, STM32F103xx, medium-density and high-density value line bootloader title and overview.</p>
30-Jul-2012	14	<p>Added information related to STM32F051x6/STM32F051x8 and to High-density ultralow power STM32L151xx, STM32L152xx bootloader.</p> <p>Added case of BOOT1 bit in Section 3.1: Bootloader activation.</p> <p>Updated Connectivity line, High-density ultralow power line, STM32F2xx and STM32F4xx in Table 3: Embedded bootloaders.</p> <p>Added bootloader version V2.2 in Table 7: STM32F105xx and STM32F107xx bootloader versions.</p> <p>Added bootloader V2.2 in Section 5.4.1: How to identify STM32F105xx/107xx bootloader versions.</p> <p>Added note related to DFU interface below Table 14: STM32L1xx High-density configuration in System memory boot mode. Added V4.2 bootloader know limitations and updated description, and added V4.5 bootloader in Table 15: STM32L1xx High-density bootloader versions.</p> <p>Added note related to DFU interface below Table 19: STM32F2xx configuration in System memory boot mode. Added V3.2 bootloader know limitations, and added V3.3 bootloader in Table 21: STM32F2xx bootloader V3.x versions. Updated STM32F2xx and STM32F4xx system memory end address in Table 22: STM32F4xx configuration in System memory boot mode.</p> <p>Added note related to DFU interface below Table 22: STM32F4xx configuration in System memory boot mode. Added V3.0 bootloader know limitations, and added V3.1 bootloader in Table 24: STM32F4xx bootloader version.</p> <p>Added bootloader V2.1 know limitations in Table 26: STM32F051xx bootloader versions.</p> <p>Updated STM32F051x6/x8 system memory end address in Table 27: Bootloader device-dependant parameters.</p> <p>Added Table 33: USART bootloader timings for STM32L15xx high-density ultralow power devices, and Table 36: USART bootloader timings for STM32F051x6 and STM32F051x8 devices.</p> <p>Added Table 38: USB minimum timings for STM32L15xx high-density ultralow power devices.</p>

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